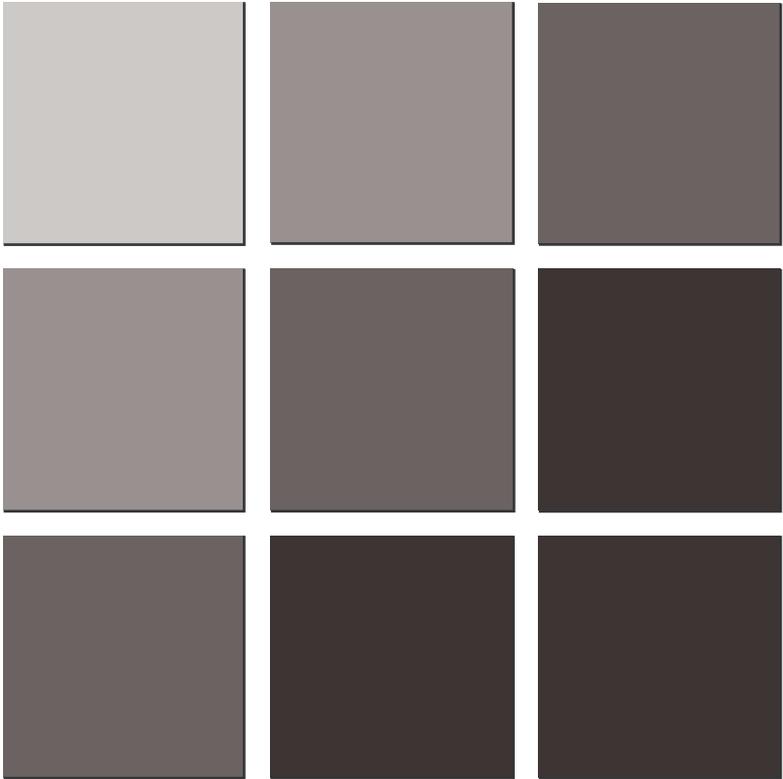


2008.1
Product Guide

[ASSP · Memory · ASIC]



Technical Documentation of Electronic Devices

DATA BOOK
(DVD)

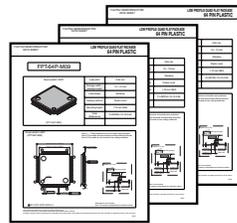
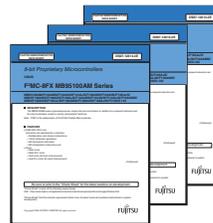
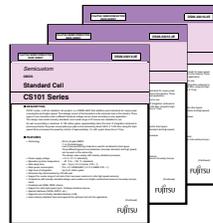
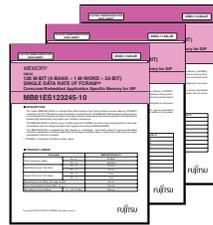
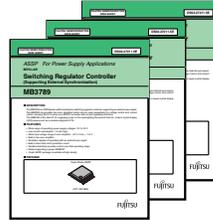


PRODUCT GUIDE
(GENERAL)

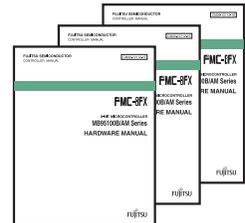


[ASSP-Memory-ASIC]

DATA SHEET



MANUAL



ASSP

Memory

ASIC

Microcontroller

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* : SPANSION™ Products

ASSP

Memory

ASIC

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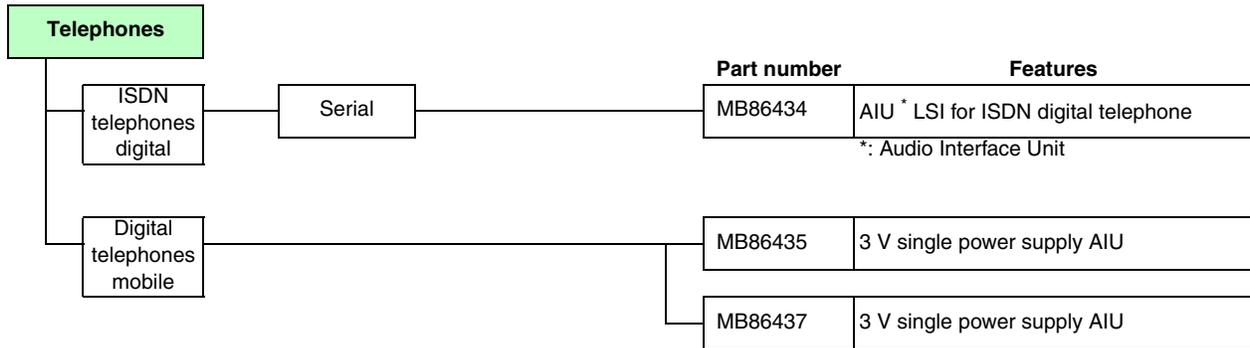
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ASSP Product Line-up

ASSP Product Line-up

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Telephone Products



■ Telephone Products

ISDN Digital Telephone LSIs

Part number	Functions	CODEC	Power supply voltage (V)	Package
				QFP
MB86434	AIU for ISDN digital telephones CODEC, DTMF tones, service tone Internal ringer tone	A-laW μ -laW 14-bit linear	+5 \pm 5%	64P

Package: P - Plastic

LSIs for Digital Mobile Telephones

Part number	Functions	Compression law	Power supply voltage (V)	Package
				LQFP
MB86435	3 V single power supply AIU	A-laW μ -laW linear	2.7 to 3.6	64P
MB86437				48P

Package: P - Plastic

Wireless Communication Products

Wireless Communication		Input frequency band of prescaler	PLL type	Prescaler divide ratio	Part number	Features
PLL Frequency Synthesizers	Low Noise Single Integer-N PLL	100 MHz to 2.5 GHz	RF Integer-N	32/33, 64/65	MB15E07SR	For digital telecommunications equipment, Low noise
		700 MHz to 3.0 GHz	RF Integer-N	64/65, 128/129	MB15E06SR	For digital telecommunications equipment, Low noise
		300 MHz to 2.0 GHz	RF Integer-N	64/65, 128/129	MB15E05SR	For digital telecommunications equipment, Low noise
	Single Integer-N PLL	700 MHz to 2.5 GHz	RF Integer-N	32/33, 64/65	MB15E07SL	For digital telecommunications equipment, Low power dissipation
		100 MHz to 2.0 GHz	RF Integer-N	64/65, 128/129	MB15E05SL	For digital telecommunications equipment, Low power dissipation
		100 MHz to 1.2 GHz	RF Integer-N	64/65, 128/129	MB15E03SL	For digital telecommunications equipment, Low power dissipation

Integer-N :Integer-N technology
 Sigma-Delta:Sigma-Delta fractional-N technology

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Wireless Communication Products

Wireless Communication Products

PLL Frequency Synthesizers

- Low Noise Single Integer-N PLL

Part number	Input frequency band (Hz)		PLL Type	Divide ratio				Power supply current typ (mA)	Power save current typ (μA)	Power supply voltage (V)			Package	
	min	max		Prescaler	Program counter	Swallow counter	Reference counter			min	typ	max	BCC	TSSOP
MB15E07SR	100M	2.5G	Integer -N	32/33, 64/65	Binary 11bit 3 to 2047	Binary 7bit 0 to 127	Binary 14bit 3 to 16383	8.0	0.1	2.7	3.75	5.0	16P	16P
								7.0	0.1	2.7	3.0	5.0		
MB15E06SR	700M	3.0G		64/65, 128/129				8.0	0.1	2.7	3.0	4.0	16P	16P
MB15E05SR	300M	2.0G		64/65, 128/129				7.0	0.1	2.7	3.75	5.0	16P	16P
								6.0	0.1	2.7	3.0	5.0		

Package: P - Plastic

- Single Integer-N PLL

Part number	Input frequency band (Hz)		PLL Type	Divide ratio				Power supply current typ (mA)	Power save current typ (μA)	Power supply voltage (V)			Package	
	min	max		Prescaler	Program counter	Swallow counter	Reference counter			min	typ	max	SSOP	BCC
MB15E07SL	700M	2.5G	Integer -N	32/33, 64/65	Binary 11bit 3 to 2047	Binary 7bit 0 to 127	Binary 14bit 3 to 16383	4.5	0.1	2.4	3.0	3.6	16P	16P
MB15E05SL	100M	2.0G		64/65, 128/129	Binary 11bit 3 to 2047	Binary 7bit 0 to 127	Binary 14bit 3 to 16383	3.5	0.1	2.4	3.0	3.6	16P	16P
MB15E03SL		1.2G		64/65, 128/129	Binary 11bit 3 to 2047	Binary 7bit 0 to 127	Binary 14bit 3 to 16383	2.5	0.1	2.4	3.0	3.6	16P	16P

Package: P - Plastic

ASSP

Wireless Communication Products

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	Input frequency band of prescaler	PLL type	Prescaler divide ratio	Part number	Features
Dual Integer-N PLL	400 MHz to 2.6 GHz	RF Integer-N	32/33, 64/65	MB15F78UL	For digital telecommunications equipment Low noise Low power dissipation
	100 MHz to 1.2 GHz	IF Integer-N	16/17, 32/33		
	2.0 GHz to 6.0 GHz	RF Integer-N	6.0G : 16/17, 32/33	MB15F76UL	For digital high-speed telecommunications equipment
	100 MHz to 1.5 GHz	IF Integer-N	1.5G : 4/5, 8/9 (Fixed part 4 division)		
	2.0 GHz to 4.0 GHz	RF Integer-N	4.0G : 64/65, 128/129	MB15F74UV	Small Package For digital high-speed telecommunications equipment
	200 MHz to 2.0 GHz	IF Integer-N	2.0G : 32/33, 64/65		
				MB15F74UL	For digital high-speed telecommunications equipment
	200 MHz to 2.25 GHz	RF Integer-N	2.25G : 64/65, 128/129	MB15F73UV	Small Package For digital high-speed telecommunications equipment
	50 MHz to 600 MHz	IF Integer-N	600M : 8/9, 16/17		
				MB15F73UL	For digital high-speed telecommunications equipment
	100 MHz to 1.3GHz	RF Integer-N	1.3G : 64/65, 128/129	MB15F72UV	Small Package For digital high-speed telecommunications equipment
	50 MHz to 350 MHz	IF Integer-N	350M : 8/9, 16/17		
				MB15F72UL	For digital high-speed telecommunications equipment
	500 MHz to 2.6 GHz	RF Integer-N	32/33, 64/65	MB15F30UV	Small Package For digital high-speed telecommunications equipment Low power dissipation
	45 MHz to 510 MHz	IF Integer-N	8/9, 16/17		
	100 MHz to 1.1GHz	RF Integer-N	1.1G : 64/65, 128/129	MB15F07SL	For digital high-speed telecommunications equipment Low noise
	100 MHz to 1.1GHz	IF Integer-N	1.1G : 64/65, 128/129		

Integer-N :Integer-N technology
Sigma-Delta:Sigma-Delta fractional-N technology

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Wireless Communication Products

• Dual Integer-N PLL

Part number	Input frequency band (Hz)		PLL Type	Divide ratio				Power supply current typ (mA)	Power save current typ (μA)	Power supply voltage (V)			Package	
	min	max		Prescaler	Program counter	Swallow counter	Reference counter			min	typ	max	BCC	TSSOP
MB15F74UV	2.0G 200M	4.0G 2.0G	Integer -N	RF : 64/65, 128/129 IF : 32/33, 64/65	Binary 11 bit 3 to 2047	Binary 7bit 0 to 127	Binary 14bit 3 to 16383	6.5 2.5	0.1 0.1	2.7 3.0	3.6 3.6	18P	-	
MB15F73UV	200M 50M	2.25G 600M		RF : 64/65, 128/129 IF : 8/9, 16/17				2.0 1.2	0.1 0.1	2.4 2.7	3.6 3.6	18P	-	
MB15F72UV	100M 50M	1.3G 350M		RF : 64/65, 128/129 IF : 8/9, 16/17				1.5 1.0	0.1 0.1	2.4 2.7	3.6 3.6	18P	-	
MB15F30UV	500M 45M	2.6G 510M		RF : 32/33, 64/65 IF : 8/9, 16/17	Binary 11 bit 3 to 2047	Binary 7bit 0 to 63	Binary 15bit 3 to 32768	2.8 1.2	0.1 0.1	2.4 2.7	3.6 3.6	18P	-	
MB15F78UL	400M 100M	2.6G 1.2G		RX : 32/33, 64/65 TX : 16/17, 32/33	Binary 11 bit 3 to 2047	Binary 7bit 0 to 127	Binary 14bit 3 to 16383	2.8 1.7	0.1 0.1	2.4 2.7	3.6 3.6	20P	20P	
MB15F76UL	2.0G 100M	6.0G 1.5G		RF : 16/17, 32/33 (Fixed part 4 division) IF : 4/5, 8/9 (Fixed part 4 division)	Binary 13bit 3 to 8191	Binary 5bit 0 to 31	Binary 14bit 3 to 16383	6.2 2.3	0.1 0.1	2.5 3.0	3.6 3.6	20P	-	
MB15F74UL	2.0G 200M	4.0G 2.0G		RF : 64/65,128/129 IF : 32/33,64/65	Binary 11bit 3 to 2047	Binary 7bit 0 to 127	Binary 14bit 3 to 16383	6.5 2.5	0.1 0.1	2.7 3.0	3.6 3.6	20P	-	
MB15F73UL	200M 50M	2.25G 600M		RF : 64/65,128/129 IF : 8/9,16/17				2.0 1.2	0.1 0.1	2.4 2.7	3.6 3.6	20P	20P	
MB15F72UL	100M 50M	1.3G 350M		RF : 64/65,128/129 IF : 350M: 8/9,16/17				1.5 1.0	0.1 0.1	2.4 2.7	3.6 3.6	20P	20P	
MB15F07SL	100M 100M	1.1G 1.1G		64/65,128/129 64/65,128/129				Binary 11bit 3 to 2047	Binary 7bit 0 to 127	Binary 14bit 3 to 16383	5.5 5.5	0.1 0.1	2.5 3.0	3.6 3.6

Package: P - Plastic

ASSP

Wireless Communication Products

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	Input frequency band of prescaler	PLL type	Prescaler divide ratio	Part number	Features
Single Sigma-Delta Fractional-N PLL	100 MHz to 2.0 GHz	RF Sigma-Delta	16/17/18	MB15E65UV	High-speed lock-up/Low noise Modulo : $2^{18}/2^{15}$
	1.0 GHz to 3.5 GHz	RF Sigma-Delta	16/17/18	MB15E64UV	High-speed lock-up/Low noise Modulo : $2^{18}/2^{15}$
Single Sigma-Delta Fractional-N PLL (RF) & Integer-N PLL (IF)	100MHz to 2.0 GHz	RF Sigma-Delta	16/17, 20/21	MB15F63UL	High-speed lock-up Modulo : 2^{20} LPF switch
	100 MHz to 600MHz	IF Integer-N	8/9, 16/17		
IF Band Integer-N PLL	233.15/259.20MHz	IF Integer-N	16/17	MB15C101	IF PLL for PHS With no external setting of a divide ratio
	10 to 330MHz (1.2 V to 1.5 V)	IF Integer-N	64/65	MB15C02	Low voltage Low power dissipation With setting of a divide ratio

Integer-N :Integer-N technology
Sigma-Delta:Sigma-Delta fractional-N technology

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Wireless Communication Products

• Single Sigma-Delta Fractional-N PLL

Part number	Input frequency band (Hz)		PLL Type	Divide ratio				Power supply current typ (mA)	Power save current typ (μA)	Power supply voltage (V)			Package
	min	max		Prescaler	Program counter	Swallow counter	Reference counter			min	typ	max	
MB15E65UV	100 M	2.0 G	Sigma-Delta	16/17/18	Binary 8 bit 9 to 255	Binary 4 bit 0 to 15	Binary 6 bit 1 to 63	4.6	0.1	2.7	3.0	3.3	18P
MB15E64UV	1.0 G	3.5 G		16/17/18	Binary 8 bit 9 to 255	Binary 4 bit 0 to 15	Binary 6 bit 1 to 63	4.6	0.1	2.7	3.0	3.3	18P

Package: P - Plastic

• Single Sigma-Delta Fractional-N PLL (RF) & Integer-N PLL (IF)

Part number	Input frequency band (Hz)		PLL Type	Divide ratio				Power supply current typ (mA)	Power save current typ (μA)	Power supply voltage (V)			Package
	min	max		Prescaler	Program counter	Swallow counter	Reference counter			min	typ	max	
MB15F63UL	100M 100M	2.0G 600M	Sigma-Delta, Integer-N	RF : 16/17, 20/21, IF : 8/9,16/17	Binary 7bit 5 to 127(RF) Binary 11bit 3 to 2047(IF)	Binary 4bit 0 to 15(RF) Binary 7bit 0 to 127(IF)	Binary 6bit 1 to 63(RF) Binary 14 bit 3 to 16383(IF)	6.1 1.4	0.1 0.1	2.7	3.0	3.3	20P

Package: P - Plastic

• IF Band Integer-N PLL

Part number	Input frequency band (Hz)		PLL Type	Divide ratio				Power supply current typ (mA)	Power save current typ (μA)	Power supply voltage (V)			Package
	min	max		Prescaler	Program counter	Swallow counter	Reference counter			min	typ	max	
MB15C101	233.15 259.20		Integer-N	16/17	291 33	7 12	384 40	1.0	-	2.4	3.0	3.6	8P
MB15C02	10 M	330M	Integer-N	64/65	12bit, 5 to 4095	6bit, 0 to 63	14bit, 16 to 16383	1.0	70	1.0	1.2	1.5	16P 20P

Package: P - Plastic

Wireless Communication Products

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	Frequency band	Part number	Features
Short distance communication	430 MHz	MB15H121	Prescaler divide ratio 8/9 PA, $\Sigma\Delta$ PLL, FSK-MOD, LNA, MIXER, LIMAMP, RSSI, FSK-DEM, VCO TANK circuit (internal)
Semicustom IF PLL	to 300 MHz (2.4 to 3.6 V) to 380 MHz (2.4 to 3.0 V) to 500 MHz (2.4 to 3.6 V)	MB15C100 series	Prescaler divide ratio 8/9, 16/17, 32/33 to 380 MHz : Vin = -10 to +2 dBm to 500 MHz : Vin = -5 to +2 dBm

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Wireless Communication Products

• Specific power saving communication

Part number	Application	Frequency band (MHz)	Functions	Power supply current typ (mA)	Power save current typ (μ A)	Power supply voltage (V)			Package
						min	typ	max	
MB15H121	Telemeter telecontroller security	430	Prescaler divide ratio 8/9 PA, $\Sigma\Delta$ PLL, FSK-MOD, LNA, MIXER, LIMAMP, RSSI, FSK-DEM, VCO TANK circuit (internal)	6.7 (PLL) 23.0 (TX) 5.0 (RX)	0.3	2.2	2.5	2.8	48P

Package: P - Plastic

• Semicustom IF PLL

Part number (Series name)	Frequency band (MHz)	Prescaler divide ratio	Power supply current (mA)	Comparison main counter divide ratio (N)	Swallow counter divide ratio (A)	Reference counter divide ratio (R)	Power supply voltage (V)	Package	
								SSOP	BCC
MB15C100 series	to 300 ^{*1} (2.4 to 3.6 V) to 380 ^{*1} (2.4 to 3.0 V) to 500 ^{*2} (2.4 to 3.6 V)	8/9, 16/17, 32/33	1.2 (300 MHz, $V_{CC} = 3 V$)	Any value between divide-by-5 and divide-by-4095	Any value between divide-by-0 and divide-by-31	Any value between divide-by-5 and divide-by-4095	+2.4 to +3.6	8P	16P (S type)

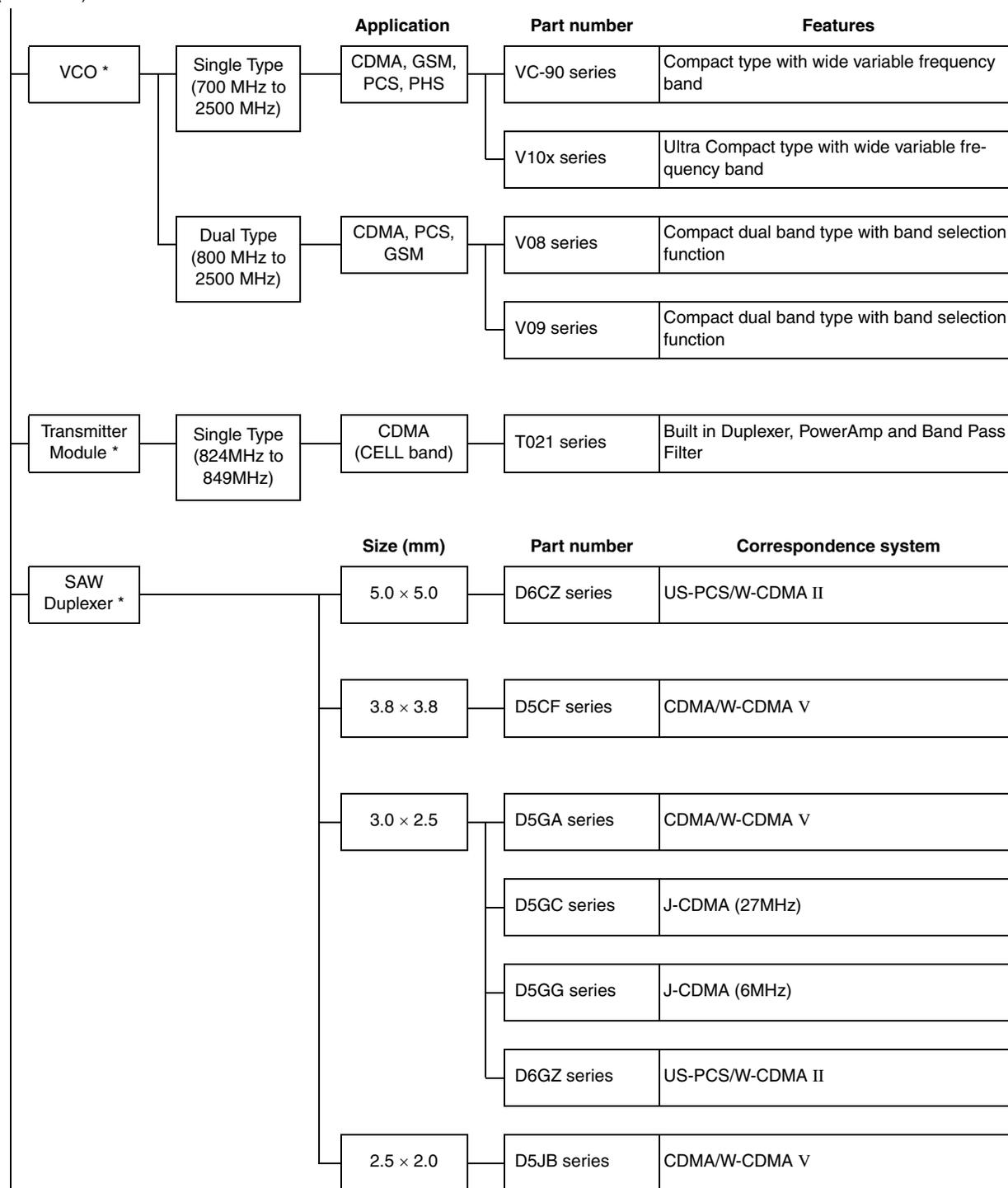
*1: Input sensitivity -10 to +2 dBm

*2: Input sensitivity -5 to +2 dBm

Package: P - Plastic

Wireless Communication Products

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Wireless Communication Products

VCO

Part number	Functions	Application	Frequency (MHz)	Power supply voltage (V)	Package Typ. (mm)
VC-90 series	Voltage Controlled Oscillator	CDMA, GSM, PCS, PHS	700 to 2500	2.5 to 3.3	5.0 × 4.0 × 1.55
V10x series					4.5 × 3.2 × 1.5
V08 series		CDMA, PCS, GSM	800 to 2500	2.8	5.5 × 4.8 × 1.8
V09 series					5.0 × 4.0 × 1.4

(Product of FUJITSU MEDIA DEVICES LIMITED)

Transmitter Module

Part number	Functions	Application	Frequency (MHz)	Power supply voltage (V)	Package Typ. (mm)
T021 series	Built in Duplexer, PowerAmp and Band Pass Filter	CDMA (CELL band)	824 to 849	3.4	8.0 × 5.0 × 1.4

(Product of FUJITSU MEDIA DEVICES LIMITED)

SAW Duplexer for Mobile Communication System

Correspondence system	Size (mm)	Part Number	Remarks
CDMA/W-CDMA V	3.8 × 3.8	FAR-D5CF-881M50-D1F1	Two types of package are available
	3.0 × 2.5	FAR-D5GA-881M50-D1AA	Two types of package are available
	2.5 × 2.0	FAR-D5JB-881 M50-D3AA	Two types of package are available
J-CDMA (27MHz)	3.0 × 2.5	FAR-D5GC-911M50-D1CA	-
J-CDMA (6MHz)	3.0 × 2.5	FAR-D5GG-872M00-D1GA	-
US-PCS/W-CDMA II	5.0 × 5.0	FAR-D6CZ-1G9600-D1XC	Two types of package are available
	3.0 × 2.5	FAR-D6GZ-1G9600-D1ZA	Two types of package are available

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Wireless Communication Products

(Continued)

	Unbalance/ balance	Size (mm)	Part number	Correspondence system
SAW Filter *	Unbalance	2.0 × 1.6	F5/F6EA series	CDMA/W-CDMA V, GSM850, EGSM, J-CDMA, DCS, US-PCS/W-CDMA II, GSM1900, W-CDMA I, GPS
		1.4 × 1.0	F5/F6KA series	CDMA/W-CDMA V, GSM850, EGSM, J-CDMA, DCS, US-PCS/W-CDMA II, GSM1900, W-CDMA I, GPS
	Balance	2.0 × 1.6	F5/F6EB series (5 pins)	CDMA/W-CDMA V, GSM850, EGSM, J-CDMA, DCS, US-PCS/W-CDMA II, GSM1900, W-CDMA I, GPS
			F6EC series (6 pins)	DCS, GSM1900, W-CDMA I
		1.4 × 1.0	F5/F6KB series	CDMA/W-CDMA V, GSM850, EGSM, J-CDMA, DCS, US-PCS/W-CDMA II, GSM1900, W-CDMA I, GPS

(Continued)

*: Product of FUJITSU MEDIA DEVICES LIMITED

Wireless Communication Products

SAW Filter for Mobile Communication System

Correspondence system	Transmission/ Reception	Size (mm)	Part number	Remarks
CDMA/W-CDMA V, GSM850	Transmission	2.0 × 1.6	FAR-F5EA-836M50-D27A	Unbalanced
		1.4 × 1.0	FAR-F5KA-836M50-D4DF	Unbalanced
			FAR-F5KB-836M50-B4EG	Balanced 200 ohm output
	Reception	2.0 × 1.6	FAR-F5EA-881M50-D27B	Unbalanced
			FAR-F5EB-881M50-B2JJ	5 pins, Balanced 100 ohm output
			FAR-F5EB-881M50-B28W	5 pins, Balanced 150 ohm output
		1.4 × 1.0	FAR-F5KA-881M50-D4CH	Unbalanced
			FAR-F5KB-881M50-B4ED	Balanced 100 ohm output
			FAR-F5KB-881M50-B4EA	Balanced 150 ohm output
			FAR-F5KB-881M50-B4EM	Balanced 150 ohm output
EGSM	Transmission	2.0 × 1.6	FAR-F5EA-897M50-D27C	Unbalanced
		1.4 × 1.0	FAR-F5KA-897M50-D4DC	Unbalanced
	Reception	2.0 × 1.6	FAR-F5EA-942M50-D27F	Unbalanced
			FAR-F5EB-942M50-B28E	5 pins, Balanced 150 ohm output
		1.4 × 1.0	FAR-F5KA-942M50-D4CJA	Unbalanced
			FAR-F5KB-942M50-B4EB	Balanced 150 ohm output
J-CDMA (32MHz)	Reception	1.4 × 1.0	FAR-F5KB-859M00-B4EE	Balanced 100 ohm output
GPS	-	2.0 × 1.6	FAR-F6EA-1G5754-L2AZ	Unbalanced
			FAR-F6EB-1G5754-B2BS	5 pins, Balanced 100 ohm output
		1.4 × 1.0	FAR-F6KA-1G5754-L4AA	Unbalanced
			FAR-F6KA-1G5754-L4AJ	Unbalanced
			FAR-F6KB-1G5754-B4GE	Balanced 100 ohm output, Low loss
			FAR-F6KB-1G5754-B4GU	Balanced 100 ohm output, High Attenuation
DCS	Reception	2.0 × 1.6	FAR-F6EA-1G8425-D2ABA	Unbalanced
			FAR-F6EB-1G8425-B2BG	5 pins, Balanced 150 ohm output
			FAR-F6EC-1G8425-B2CE	6 pins, Balanced 150 ohm output
		1.4 × 1.0	FAR-F6KA-1G8425-D4CK	Unbalanced
			FAR-F6KB-1G8425-B4GA	Balanced 150 ohm output
US-PCS/W-CDMA II, GSM1900	Transmission	2.0 × 1.6	FAR-F6EA-1G8800-L2AN	For Full Band
		1.4 × 1.0	FAR-F6KA-1G8800-L4AF	For Full Band
	Reception	2.0 × 1.6	FAR-F6EA-1G9600-D2AC	Unbalanced
			FAR-F6EB-1G9600-B2BK	5 pins, Balanced 100 ohm output
			FAR-F6EB-1G9600-B2BW	5 pins, Balanced 150 ohm output
		1.4 × 1.0	FAR-F6EC-1G9600-B2CW	6 pins, Balanced 150 ohm output
			FAR-F6KA-1G9600-D4CR	Unbalanced
			FAR-F6KB-1G9600-B4GP	Balanced 100 ohm output
			FAR-F6KB-1G9600-B4GB	Balanced 150 ohm output
W-CDMA I	Transmission	2.0 × 1.6	FAR-F6EA-1G9500-D2AL	Unbalanced
			FAR-F6KA-1G9500-D4CD	Unbalanced
		1.4 × 1.0	FAR-F6KA-1G9500-D4DG	Unbalanced
			FAR-F6KB-1G9500-B4GJ	Balanced 100 ohm input
	Reception	2.0 × 1.6	FAR-F6EB-2G1400-B2BN	5 pins, Balanced 100 ohm output
			FAR-F6EC-2G1400-B2CP	6 pins, Balanced 200 ohm output
		1.4 × 1.0	FAR-F6KA-2G1400-D4CG	Unbalanced
			FAR-F6KB-2G1400-B4GC	Balanced 100 ohm output
			FAR-F6KB-2G1400-B4GD	Balanced 200 ohm output

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Wireless Communication Products

(Continued)

	Unbalance/ balance	Size (mm)	Part number	Correspondence system
Dual SAW Filter *	Unbalance	2.5 × 2.0	G5/G6ED series	GSM850 + EGSM
		1.8 × 1.4	G5KL series	J-CDMA (27MHz + 6MHz)
	Balance	2.5 × 2.0	G5/G6EE series	EGSM + DCS, GSM850 + EGSM, DCS + GSM1900
		2.0 × 1.6	G5/G6KE series	CDMA/W-CDMA V + PCS/W-CDMA II, EGSM + DCS, GSM850 + EGSM, DCS + GSM1900
		1.8 × 1.4	G5/G6KG series	W-CDMA, EGSM + DCS, GSM850 + EGSM, DCS + GSM1900

*: Product of FUJITSU MEDIA DEVICES LIMITED

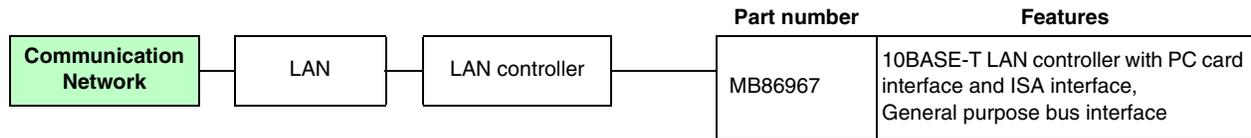
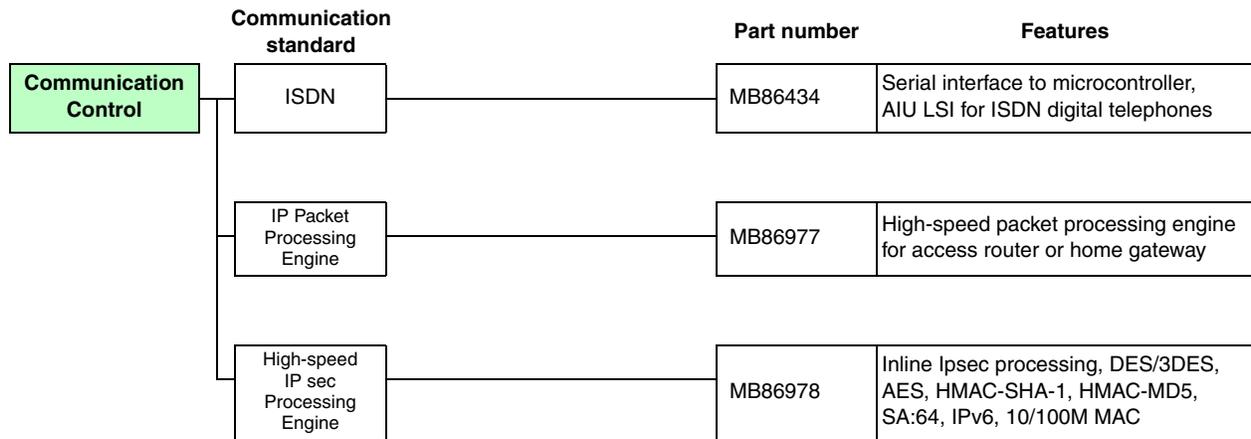
Wireless Communication Products

SAW Dual Filter for Mobile Communication System

Correspondence system	Transmission/ Reception	Size (mm)	Part number	Remarks
EGSM + DCS	Reception	2.5 × 2.0	FAR-G6EE-1G8425-Y2PN	Balanced 150 ohm output, Opposite type of Filter position is available.
		2.0 × 1.6	FAR-G6KE-1G8425-Y4QG	Balanced 150 ohm output, Opposite type of Filter position is available.
		1.8 × 1.4	FAR-G6KG-1G8425-Y4SA	Balanced 150 ohm output, Opposite type of Filter position is available.
GSM850 + EGSM	Transmission	2.5 × 2.0	FAR-G5ED-897M50-D2DE	Unbalanced
	Reception	2.5 × 2.0	FAR-G5EE-942M50-Y2PB	Balanced 150 ohm output, Opposite type of Filter position is available.
		2.0 × 1.6	FAR-G5KE-942M50-Y4QA	Balanced 150 ohm output, Opposite type of Filter position is available.
		1.8 × 1.4	FAR-G5KG-942M50-Y4SD	Balanced 150 ohm output, Opposite type of Filter position is available.
DCS + GSM1900	Reception	2.5 × 2.0	FAR-G6EE-1G9600-Y2PR	Balanced 150 ohm output, Opposite type of Filter position is available.
		2.0 × 1.6	FAR-G6KE-1G9600-Y4QB	Balanced 150 ohm output, Opposite type of Filter position is available.
		1.8 × 1.4	FAR-G6KG-1G9600-Y4SC	Balanced 150 ohm output, Opposite type of Filter position is available.
CDMA/W-CDMA V + US-PCS/W-CDMA II	Reception	2.0 × 1.6	FAR-G6KE-1G9600-Y4LY	Balanced 100 ohm output
J-CDMA (27 MHz + 6 MHz)	Transmission	1.8 × 1.4	FAR-G5KL-911M50-D4XA	Unbalanced, 1input/2output
W-CDMA I + V	Transmission	1.8 × 1.4	FAR-G6KG-1G9500-Y4PG	Balanced 200 ohm input
	Reception	1.8 × 1.4	FAR-G6KG-2G1400-Y4SH	Balanced 200 ohm output

(Product of FUJITSU MEDIA DEVICES LIMITED)

Communication Control/Communication Network



Communication Control/Communication Network

Communication Control

ISDN

Part number	Functions	Communication standard	Power supply voltage (V)	Package
				QFP
MB86434	AIU LSI for ISDN digital telephones, Internal CODEC, DTMF tones, service tone, and ringer tone	-	+5 ± 5%	64P

Package: P - Plastic

IP Packet Processing Engine

Part number	Functions	Power supply voltage (V)	Package
			LQFP
MB86977	Enable to process following functions with hardware. IP Packet Forwarding Packet Filtering NAT PPPoE and more. Supports QoS, DMZ, IPv6 and more. 10/100M MAC (Conforms to IEEE802.3)	3.3 ± 0.3 1.8 ± 0.15	208P

Package: P - Plastic

High Speed IP sec Processing Engine

Part number	Functions	Power supply voltage (V)	Package
			FBGA
MB86978	Inline Ipsec processing, DES / 3DES,AES,HMAC - SHA-1,HMAC-MD5,SA:64,IPv6,10 / 100M MAC	3.3 ± 0.3 1.8 ± 0.15	337P 288P

Package: P - Plastic

Communication Network

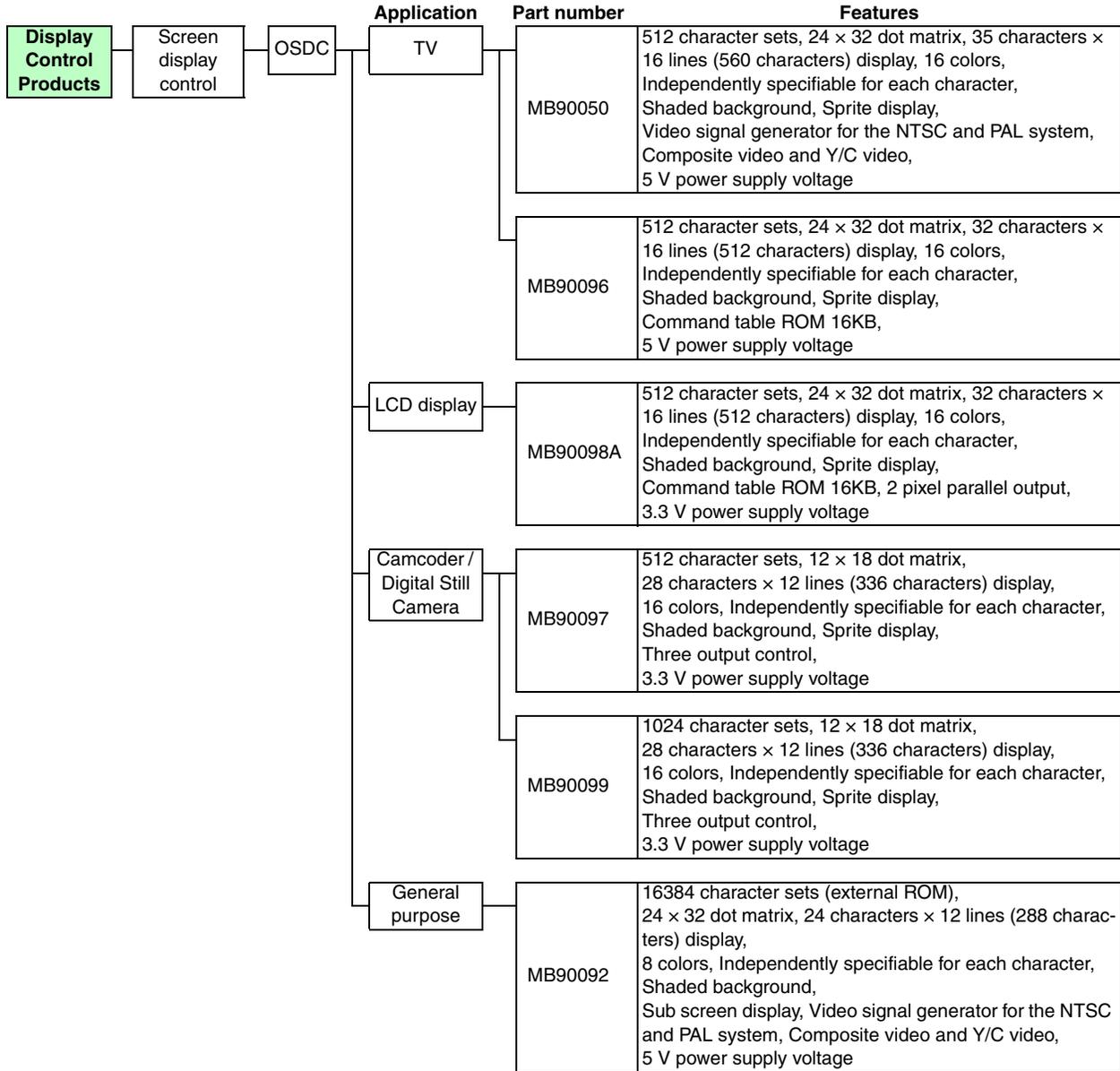
LAN

Part number	Functions	Communication standard	Power supply voltage (V)	Package
				LQFP
MB86967	10BASE-T Ethernet controller with PC card interface, ISA bus interface and General purpose bus interface	Conforms to IEEE 802.3	+5 ± 5%	100P

Note: Ethernet is a registered trademark of XEROX Corporation of the USA.

Package: P - Plastic

Display Control Products



Display Control Products

■ Display Control Products

Screen Display Control

OSDC (On-Screen Display Controller)

Part number	Character generator	Number of character set	Character dot structure	Screen size	RGB digital output	Analog (video) output	Sync signal generation	Power supply voltage (V)	Package				
									SH-DIP	SOP	QFP	SSOP	FLGA
MB90050	Internal ROM	512	24 × 32	35 characters × 16 lines	6bit (16 color selection in 64 colors)	Composite Video and Y/C video	NTSC PAL	+5 ±10%	—	—	48P	—	—
MB90096	Internal ROM			32 characters × 16 lines	4bit (16 colors)	Unavailable	Unavailable	+5 ±10%	28P	28P	—	—	—
MB90098A								—	28P	—	—	—	
MB90097			—	—	—	20P	—						
MB90099			—	—	—	20P	20P						
MB90092	External ROM	16384 (Max.)	24 × 32	24 characters × 12 lines	3bit (8 colors)	Composite Video and Y/C video	NTSC PAL	+5 ±10%	—	—	80P	—	—

Package: P - Plastic

Video/Audio Products

		Application	Frequency	Part number	Features
Video/Audio Products	IF SAW Filter *	Analog	40 to 60 MHz	F*** series F4SA series G4SB series K4SD series	Plastic package 13.7 × 5.2 × 2.1 mm For Inter carrier, Split-carrier Single, Dual, Switchable filter Small ripple in passband, high attenuation
		Digital	40 to 60 MHz	SBF series SBSF series F4SE series K4SH series	Plastic package 13.7 × 5.2 × 2.1 mm For terrestrial, CATV, Cable modem Single, Dual, Switchable filter Small ripple in passband, high attenuation
		Double conversion	1 GHz band	F6CV series	Ceramic package 2.5 × 2.0 × 1.0 mm For silicon tuner 1st interface 200 ohm I/O balance Low loss, high attenuation

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(Continued)

Video/Audio Products

IF SAW Filter for Analog

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Applicable types	System	Video/Audio	Picuture carrier frequency (MHz)	Part number
NTSC N	Inter-Carrier (single)	Video	58.75	F081EPL
	Split-Carrier (single)	Video	58.75	FAR-F4SA-58M750-A008
	Split-Carrier (single)	Video	58.75	FAR-F4SA-58M750-A019
	Split-Carrier (single)	Audio	58.75	FAR-F4SA-54M250-B011
	Split-Carrier (dual)	Video/Audio	58.75	FAR-G4SB-58M750-D018
NTSC M/N	Inter-Carrier (single)	Video	45.75	F072TPL-A
	Split-Carrier (single)	Video	45.75	FAR-F4SA-45M750-A024
	Split-Carrier (single)	Audio	45.75	FAR-F4SA-41M250-B021
	Split-Carrier (dual)	Video/Audio	45.75	FAR-G4SB-45M750-D025
PAL B/G/D/K/I	Inter-Carrier (single)	Video	38.90	FAR-F4SA-38M900-A041
	Split-Carrier (single)	Video	38.90	FAR-F4SA-38M900-A071
	Split-Carrier (single)	Video	38.90	FAR-F4SA-38M900-A072
	Split-Carrier (single)	Audio	38.00	F337MPL
	Split-Carrier (single)	Audio	38.90	FAR-F4SA-40M400-B071
PAL B/G, D/K, NTSC M/N	Split-Carrier (Switchable)	Video + Video	38.00	FAR-K4SD-38M000-F002
	Split-Carrier (Switchable)	Video + Video	38.00	FAR-K4SD-38M000-F011
	Split-Carrier (Switchable)	Video + Video	38.90	FAR-K4SD-38M900-F003
PAL D/K/I, B/G, L/L'	Split-Carrier (Switchable)	Audio + Audio	33.90/38.90	FAR-K4SD-40M400-G001
	Split-Carrier (Switchable)	Audio + Audio	33.90/38.90	FAR-K4SD-40M400-G002
	Split-Carrier (Switchable)	Audio + Audio	33.90/38.90	FAR-K4SD-40M400-G031
	Split-Carrier (dual)	Audio + Audio	33.90/38.90	F817JPL

IF SAW Filter for Digital

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Applicable types	Center frequency (MHz)	3 dB Bandwidth (MHz)	Part number
DAB	38.912	1.50	SBF0402GPL
OOB	44.000	1.70	SBF0402JPL
	44.000	1.70	FAR-F4SE-44M000-A011
	44.000	2.60	FAR-F4SE-44M000-H0A6
	44.000	4.00	FAR-F4SE-44M000-H0A3
	44.000	4.00	FAR-F4SE-44M000-H0A3
CATV/TV (US/Euro)	36.000	8.10	FAR-F4SE-36M000-A005
	36.125	6.10	FAR-F4SE-36M125-A001
	36.125	7.00	SBF0407BPL
	36.125	8.10	SBF0408KPL
	43.750	6.00	FAR-F4SE-43M750-A006
	43.750	6.00	FAR-F4SE-43M750-H0AB
	44.000	5.35	FAR-F4SE-44M000-H0AG
	44.000	5.37	FAR-F4SE-44M000-H0A4
	44.000	5.42	FAR-F4SE-44M000-H0A8
	44.000	5.49	FAR-F4SE-44M000-H0A1
	44.000	5.50	FAR-F4SE-44M000-H0AH
	44.000	6.00	FAR-F4SE-44M000-H0A9
	44.000	6.12	FAR-F4SE-44M000-H0A2
	44.000	6.20	FAR-F4SE-44M000-H0AA
	44.000	8.00	SBF0408LPL
	47.250	6.20	FAR-F4SE-47M250-H0AC
	36.000	6.4/7.4 (Switchable)	FAR-K4SH-36M000-LOE1
	36.000	7.0/7.9 (Switchable)	SBSF03ABPL
	36.125	6.0/7.9 (Switchable)	FAR-K4SH-36M125-F001
	36.125	7.0/7.9 (Switchable)	SBSF03AAPL
CATV/TV (Japan)	57.000	5.30	FAR-F4SE-57M000-H0JC
	57.000	5.40	FAR-F4SE-57M000-H0J9
	57.000	5.62	FAR-F4SE-57M000-H0J6
	57.000	5.62	FAR-F4SE-57M000-H0J3
TV tuner	35.230	8.00	FAR-F4SE-35M230-A013
	36.125	6.90	FAR-F4SE-36M125-H0E8
	36.125	7.60	FAR-F4SE-36M125-H0E5
TV/STB	36.125	7.90	FAR-F4SE-36M125-H0E7

IF SAW Filter for Double ConversionI

(Product of FUJITSU MEDIA DEVICES LIMITED)

Applicable types	Center frequency (MHz)	Bandwidth (MHz)	Part number
1st IF	1220.000	8.00	FAR-F6CV-1G2200-C27A

Video/Audio Products/Demodulator Products

(Continued)

	Application	Capacity	Organization	Part number	Features
EDID memory	DTV/display for HDMI	2K-bit	256 × 8	MB85RF402	For 4 DDC(I ² C) ports

Digital Demodulator	Application	Part number	Features
	Satellite	MB86667	Small 48 pin package High tolerance to spectrum distortion High and stability of reception Blind Scan support
	Cable	MB86668	Small 48 pin package High tolerance to spectrum distortion High and stability of reception
	Ground Wave	MB86A20	Support Japanese Terrestrial Digital TV and Digital Radio. All memory such as time-interleave is implemented. Input signal : 4MHz-IF or 57MHz-IF Output signal : serial or parallel TS

Video/Audio Products/Demodulator Products

EDID memory

Part Number	Memory	Organization (W × b)	Interface	Supply Voltage (V)	Packages
					TSSOP
○MB85RF402	FRAM	256 × 8	For 4 DDC(I ² C) ports	3.8 to 5.5	16P

○ : New released.

Package : P - Plastic

Demodulator Products

Satellite

Part number	Function	Power supply voltage (V)	Package
			QFP
MB86667	QPSK demodulator DVB-S and DSS support	1.65 to 1.95 3.0 to 3.6	48P

Package: P - Plastic

Cable

Part number	Function	Power supply voltage (V)	Package
			QFP
MB86668	QAM demodulator DVB-C support	1.65 to 1.95 3.0 to 3.6	48P

Package: P - Plastic

Ground Wave

Part number	Function	Power supply voltage (V)	Package
			FBGA
MB86A20	13 segment OFDM demodulator ISDB-T support	1.4 to 1.6 1.65 to 1.95 3.0 to 3.6	144P

Package: P - Plastic

Automotive Applications

Automotive applications	Application	Internal operation frequency	Drawing	Max. display resolution	No. of layer	Part number	Features
Graphics display controller	Car navigation system	100 MHz	2D/3D	1024 × 768	4	MB86291A	Host interface which is connectable to FR, SH3/4, and V83x 2 MB SDRAM as graphics memory 4 layers of overlay display (bottom 2 layers can both be split into separate segment) Special effect function such as alpha blending and anti-aliasing Other interface: I ² C
		133 MHz	2D/3D	1024 × 768	6	MB86293	Host interface which is connectable to FR, SH3/4, and V83x Max. 64 MB of SDRAM (connectable in external) as graphics memory (operation frequency: max. 133 MHz) Special effect function such as alpha blending and anti-aliasing
						MB86294	Host interface which is connectable to FR, SH3/4, and V83x Max. 64 MB of SDRAM (connectable in external) as graphics memory (operation frequency: max. 133 MHz) Video capture input (down scaling of the data) Special effect function such as alpha blending and anti-aliasing Other interface: I ² C
						MB86296	PCI 33 MHz host interface Max. 64 MB of SDRAM (connectable in external) as graphics memory (operation frequency: max. 133 MHz) Video capture input (up/down scaling of the data) Special effect function such as alpha blending and anti-aliasing Other interface: I ² C, SIO, GPIO
		266 MHz	2D/3D	1280 × 1024	8	MB86297A	Newly developed rendering engine (compatible to OpenGL ES 1.1 hardware acceleration) Geometry engine with 10 M polygon/sec. processing performance PCI 66 MHz host interface Max. 128 MB of DDR-SDRAM (connectable in external) as graphics memory (operation frequency: max. 133 MHz) Video capture input for 2ch (up/down scaling of the data) 8 bit digital RGB output for 2ch Other interface: I ² C
	Instrument panel	133 MHz	2D	1280 × 768	6	MB86276	Host interface which is connectable to FR, SH3/4, and V83x Max. 64 MB of SDRAM (connectable in external) as graphics memory (operation frequency: max. 133 MHz) Video capture input (up/down scaling of the data) Other interface: I ² C

Automotive Applications

Graphics Display Controller

Part number	Internal operation frequency	Rendering engine	Geometry engine	Max. graphics memory	Drawing	Display resolution (pixel)	No. of layer	Texture mapping (pixel)	Video capture input	Video scaling	Video output	Host interface	Power supply voltage (standard value)	Operation temp. range (°C)	Package				
MB86291A	100 MHz	Built-in	Built-in	2 MB SDRAM (built-in)	2D/3D	Max. 1024 × 768	4	Max. 256 × 256	YUV	-	RGB analog/digital	32 bit parallel	I/O: 3.3 V Internal: 2.5 V	-30 to +85	QFP-208P				
MB86293	133 MHz			64 MB SDRAM (external)			6 (included 1 alpha plane)	Max. 4096 × 4096	-	-	RGB digital		PCI 33 MHz		I/O: 3.3 V Internal: 1.8 V	QFP-256P			
MB86294																YUV	Down	RGB analog/digital	QFP-256P BGA-256P
MB86296																YUV/RGB	Up/Down	RGB digital × 2	BGA-256P
MB86297A	266 MHz			128 MB DDR-SDRAM (external)			8 (plus 4 alpha plane)	YUV × 2/RGB + YUV	Up/Down	RGB digital × 2	PCI 66 MHz		I/O: 3.3 V Internal: 1.2 V		TEBGA-543P				
MB86276	133 MHz			-			64 MB SDRAM (external)	2D	Max. 1280 × 768	6 (included 1 alpha plane)	YUV/RGB		Up/Down		RGB digital	32/16 bit parallel Address/data bus multiplex	I/O: 3.3 V Internal: 1.8 V	PBGA-320P	

Packages: P - Plastic

Power Management Applications

Power Management Applications	Oscillator frequencies (kHz)	Error amplifiers	Part number	Features		
AC/DC converters	300	Operational amplifier type	MB3759	Push-pull, Single-end function switchable, TL494-equivalent		
		Operational amplifier type	MB3769A	MOS FET compatible, Dynamic over-current detection		
General purpose DC/DC converters	1	200	Operational amplifier type	MB3789	Adaptable for external CLK synchronization, Two internal error amplifiers, Soft-start, Timer-latch type short circuit protection	
			Operational amplifier type	MB3817	Soft-start, Timer-latch type short circuit protection	
		500	Operational amplifier type	MB3885	N/N synchronous rectification, Over voltage protection, Soft-start, Timer-latch type short circuit protection	
			Fixed gain type	MB3800	Low voltage operation,, Soft-start, Timer-latch type short circuit protection	
		1000	Operational amplifier type	MB39A135	N/N synchronous rectification, Current mode type, Over voltage protection, Over current detection, Over thermal protection, Soft-start/stop	
			500	Fixed gain type	MB3775	Open collector, Timer-latch type short circuit protection
		Operational amplifier type		MB3778	Open collector, Timer-latch type short circuit protection	
		2	500	Operational amplifier type	MB3882	N/N synchronous rectification, Over voltage protection, Soft-start, Timer-latch type short circuit protection
				Operational amplifier type	MB3889	N/N synchronous rectification, Timer-latch type over voltage protection , Timer-latch type over current protection, POWERGOOD circuit, Symmetrical-Phase method, Soft-start/stop
			1000	Operational amplifier type	MB39A106	N/N synchronous rectification, Boot strap diode, Timer-latch type over voltage protection , Timer-latch type over current protection, POWERGOOD circuit, Soft-start/stop, Symmetrical-Phase method
				Operational amplifier type	MB39A116A	N/N synchronous rectification, Boot strap diode, Over voltage protection, Timer-latch type over current protection , POWERGOOD circuit, Soft-start/stop
			1000	Operational amplifier type	MB39A136	N/N synchronous rectification, Current mode type, Over voltage protection , Over current detection, Over thermal protection, Soft-start/stop
			1500	Operational amplifier type	MB39A104	Soft-start, Timer-latch type short circuit protection , Timer-latch type over current protection
		2000	Operational amplifier type	MB39C011 MB39C011A	P/N synchronous rectification (P-ch. asynchronous rectification) , Soft-start, Timer-latch type short circuit protection ,	
3	500	Operational amplifier type	MB3782	Open collector, Timer-latch type short circuit protection		
		Operational amplifier type	MB39A112	P-ch. asynchronous rectification , Each channel control, Soft-start		

(Continued)

Power Management Applications

Power Management Applications

AC/DC Converters

Part number	Function	Power supply voltage (V)	No. of channels	Operating oscillator frequency (kHz) (Max.)	Reference voltage (V) (Typ.)		Package SOP
						Precision (%)	
MB3759	PWM-type controllers for AC/DC converters	+7 to +32	1	300	5	5.0	16P
MB3769A		+12 to +18		700		2.0	16P

Packages: P - Plastic

General Purpose DC/DC Converters

Part number	Function	Power supply voltage (V)	No. of channels	Operating oscillator frequency (kHz) (Max.)	Reference voltage (V) (Typ.)		Solutions	Package		
						Precision (%)		SOP	SSOP	TSSOP
MB3789	PWM-type controllers for DC/DC converters	+3.0 to +18	1	200	2.5	4.0	Up conversion	-	16P	-
MB3817		+2.5 to +18		500	1.5	2.0	Up conversion Down conversion Invert	-	16P	-
MB3885		+5.5 to +18			1.25	1.0	Down conversion	-	20P	-
MB3800		+1.8 to +15		1000	0.5	4.0	Up conversion	8P	8P	-
○MB39A135		+4.5 to +25			0.7	1.0	Down conversion	-	-	24P
MB3775	PWM-type controllers for DC/DC converters	+3.6 to +18	2	500	1.28	1.5	Up conversion Down conversion Invert	16P	16P	-
MB3778					2.46	2.0		16P	16P	-
MB3882					1.25	1.0	Down conversion	-	24P	-
MB3889		1.23		-				-	30P	
MB39A106		+6.5 to +18		1.00	1.0	Down conversion	-	-	30P	
MB39A116A							-	-	30P	
○MB39A136		+4.5 to +25		1000	0.7	-	-	16P		
MB39A104		+7 to +19		1500	1.24	-	24P	-		
MB39C011 MB39C011A		+4.5 to +17		2000	1.0	-	-	16P		
MB3782	PWM-type controllers for DC/DC converters	+3.6 to +18	3	500	2.5	2.0	Up conversion Down conversion Invert	20P	-	-
MB39A112		+7 to +25		2600	(1.0/ 1.23)	1.0	Down conversion	-	-	20P

○: New product

Packages: P - Plastic

Power Management Applications

(Continued)

	Number of Channels	Oscillator frequencies (kHz)	Error amplifiers	Part number	Features		
DC/DC converters with switching FET	1	2000/3000	Fixed gain type	MB39C014	Current mode type, Synchronous rectification, short circuit protection, Over current detection, Over thermal protection, POWERGOOD		
	2	2000	Fixed gain type	MB39C015	Current mode type, Synchronous rectification, short circuit protection, Over current detection, Over thermal protection, Voltage detection circuit		
LDO + DC/DC converters with switching FET	2 *	2000	Operational amplifier type	MB39C022G	Current mode type, Synchronous rectification, short circuit protection, Over current protection, Over thermal protection, POWERGOOD, Monitoring of output voltage *: 1 ch. is LDO, 1 ch. is DC/DC converter.		
DC/DC converters for RF Power Amp.	1	2000	Fixed gain type	MB39C018	Current mode type, Built-in Bypass FET, Synchronous rectification, Output current 800mA (Max.)		
DSC/camcorder DC/DC converters	4	1000	Operational amplifier type	MB3785A	Internal high-precision reference voltage circuit, Channel on/off control function		
		1500	Operational amplifier type	MB39A102	Support for control and soft-start of each channel, High-precision reference voltage, Support for external input short detection		
				MB39A103	Low voltage operation, Support for control and soft-start of each channel, High-precision reference voltage, Support for external input short detection.		
		2000	Operational amplifier type	MB39A110	Synchronous rectification Support for control and soft-start of each channel, High-precision reference voltage, Support for external input short detection		
	5	2000	Operational amplifier type	MB39A108	Low voltage operation, Synchronous rectification, Supports for control and soft-start of each channel, High-precision reference voltage, Support for external input short detection		
				MB39A115	Synchronous rectification, Supports for control and soft-start of each channel, High-precision reference voltage, Support for external input short detection		
	6	800	Operational amplifier type	MB3825A	High-precision reference voltage, Synchronous rectification		
				1000	Operational amplifier type	MB3883	Low voltage operation, High-precision reference voltage, Synchronous rectification
				2000	Operational amplifier type	MB39A123	Low voltage operation, Synchronous rectification, Supports for control and soft-start of each channel, High-precision reference voltage, Support for external input short detection
	8	800	Operational amplifier type	MB3881	Low voltage operation, High-precision reference voltage, Synchronous rectification,		

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Power Management Applications

DC/DC converters with switching FET

Part number	Function	Power supply voltage (V)	No. of channels	Operating oscillator frequency (kHz) (Max.)	Reference voltage		Output current		Switching FET ON resistance		Solutions	Package	
					(V) (Typ.)	Precision (%)	DC/DC (mA) (Max)	Bypass FET (mA) (Max)	Pch MOS (Ω) (Typ)	Nch MOS (Ω) (Typ)		QFN	SON
MB39C014	PWM type DC/DC converters	+2.5 to +5.5	1	2000/3200 (Fix)	1.20	2.0	800	0.3	0.2	Down conversion	—	10P	
MB39C015			2	2000 (Fix)	1.30						24P	—	

Packages: P - Plastic

DC/DC converters with switching FET + LDO

Part number	Function	Power supply voltage (V)	No. of channels	Operating oscillator frequency (kHz)	Reference voltage (V) (Typ.)	Output voltage (V) (Typ.)	Precision (%)	Output current (mA) (Max.)	Switching FET ON resistance		I/O potential drop (mV) (Typ.)	Solutions	Package	
									Pch MOS (Ω) (Typ)	Nch MOS (Ω) (Typ)			QFN	SON
©MB39C022G	DC/DC converter	+2.5 to +5.5	1	2000 (Fix)	0.3	—	±2.5	600	0.3	0.2	—	Down conversion	10P	
	LDO		1	—	—	3.3 (Fix)	±2.5	300	—	—	200 (Io = -300mA)			

©: Now planning

Packages: P - Plastic

DC/DC converters for RF Power Amp.

Part number	Function	Power supply voltage (V)	No. of channels	Operating oscillator frequency (kHz) (Max.)	Reference voltage		Output current		Switching FET ON resistance			Solutions	Package	
					(V) (Typ.)	Precision (%)	DC/DC (mA) (Max)	Bypass FET (mA) (Max)	Pch MOS (Ω) (Typ)	Nch MOS (Ω) (Typ)	Bypass FET (Ω) (Typ)		QFN	SON
MB39C018	PWM type DC/DC converters Built in Bypass FET	+2.5 to +5.5	1	2000 (Fix)	1.24	1.5	800	1000	0.3	0.2	0.08	Down conversion	24P	

Packages: P - Plastic

DSC/Camcorder DC/DC Converters

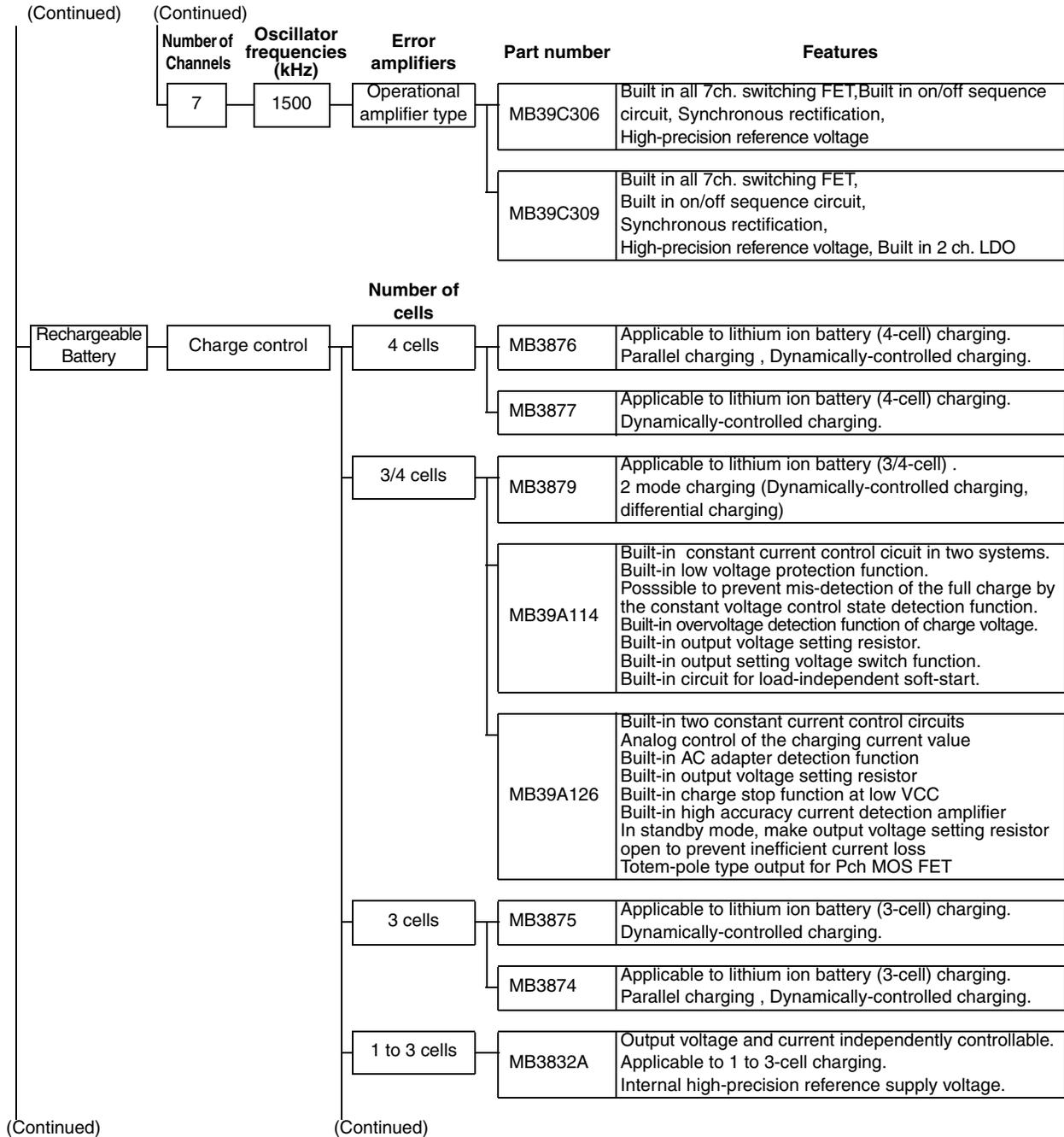
Part number	Function	Power supply voltage (V)	No. of channels	Operating oscillator frequency (kHz) (Max.)	Reference voltage		Solutions	Drive circuit	Package		
					(V) (Typ.)	Precision (%)			LQFP	BCC	TSSOP
MB3785A	PWM-type controllers for DC/DC converters	+4.5 to +18	4	1000	2.5	1.0	Down conversion	PNP : 4	48P	—	—
MB39A102		+2.5 to +11		1500	2.0		Up conversion Down conversion Up/Down conversion	Pch : 3, Nch : 1	—	32P	30P
MB39A103		+1.7 to +11						Pch : 1, Nch : 3	—	32P	30P
MB39A110		+2.5 to +11		Pch : 3, Nch : 1	—		—	38P			
MB39A108		+1.7 to +11	5	2000	2.0		Up conversion Down conversion Up/Down conversion Invert	Pch : 3, Nch : 2	—	40P	38P
MB39A115								Pch : 4, Nch : 1	—	40P	38P
MB3825A		+2.5 to +12	6	800	1.5		Down conversion	PNP : 6	64P**	—	—
MB3883		+1.7 to +9		1000	2.5		Up conversion Down conversion Up/Down conversion	Pch : 2, Nch : 4	48P	48P	—
MB39A123		+1.7 to +11						2000	2.0	Up conversion Down conversion Up/Down conversion Invert	Pch : 4, Nch : 2
MB3881		+1.8 to +13		8	800		2.5				Down conversion Up/Down conversion

*: 0.4 mm pitch

** : 0.4 mm pitch, 0.5 mm pitch

Packages: P - Plastic

Power Management Applications



Power Management Applications

DSC/Camcorder DC/DC Converters

Part number	Function	Power supply voltage (V)	No. of channels	Operating oscillator frequency (kHz) (Max.)	Reference voltage		Solutions	Drive circuit	Package
					(V) (Typ.)	Precision (%)			FBGA
MB39C306	PWM-type DC/DC converters	+2.5 to +6	7	1500	2.4	1.0	Up conversion Down conversion Up/Down conversion Invert	All channel with built-in switching FETs	103P
MB39C309		+2.5 to +5.5	7 (DC/DC) 2 (LDO)						82P

Packages: P - Plastic

Rechargeable Battery (Charge control)

Part number	Function	Power supply voltage (V)	Output voltage (V)	Precision (%)		Number of cells	Operating oscillator frequency (kHz) (Max.)	Solutions	Package		
				Ta = +25 °C	Ta = -30 to +85 °C				SSOP	LQFP	QFN
				MB3876	Charge control DC/DC converters				+7 to +25	16.8	±0.8
MB3877	24P	-	-								
MB3879	+8 to +25	12.6/16.8	±0.8	±1.0		3/4	-	48P	-		
		12.3/16.4	±0.9	±1.1							
MB39A114	+8 to +25	12.6/16.8	±0.5	±0.74 *		3/4	24P	-	-		
MB39A126			±0.6	±0.80 *			24P	-	28P		
MB3875	+7 to +25	12.6	±0.8	±1.0		3	24P	-	-		
MB3874							24P	-	-		
MB3832A	+3.6 to +18	Any voltage level	±0.5	±1.0*	1 to 3	20P	-	-			

* : Ta = -10 to +85 °C

Package: P-plastic

Power Management Applications

(Continued)

(Continued)

Number of cells	Part number	Features
1 to 4 cells	MB3878	Output voltage and current are independently controllable. Applicable to 1 to 4-cell charging. Internal high-precision reference supply voltage, Dynamically-controlled charging.
	MB3887	Output voltage and current are independently controllable. Applicable to 1 to 4-cell charging. Internal high-precision reference supply voltage. High charging current accuracy. Dynamically-controlled charging.
	MB3888	Output voltage and current are independently controllable. Applicable to 1 to 4-cell charging. Internal high-precision reference supply voltage. High charging current accuracy.
	MB39A113	Built-in constant current control circuit in two systems. Built-in low voltage protection function. Possible to prevent mis-detection of the full charge by the constant voltage control state detection function. Built-in overvoltage detection function of charge voltage. Built-in circuit for load-independent soft-start.
	MB39A118	Built-in off time control function, Built-in constant current control circuit in two systems, Possible to control of the constant current by analog value, Built-in for Nch MOS FET synchronous rectification type output stage, Built-in battery select function, Possible to set any output voltage by external resistor, In IC standby mode, leave output voltage setting resistor open to prevent inefficient current loss
	MB39A119	Built-in off time control function, Built-in voltage detection function of AC adapter, Possible to prevent mis-detection of the full charge by the constant voltage control state detection function, Built-in constant current control circuit in two systems, Possible to control of the constant current by analog value, Built-in for Nch MOS FET synchronous rectification type output stage, Built-in charge stop function at low VCC, Possible to set any output voltage by external resistor, In IC standby mode, leave output voltage setting resistor open to prevent inefficient current loss
	MB39A125	Built-in two constant current control circuits, Analog control of the charging current value, Built-in AC adapter detection function, External output voltage setting resistor, Built-in charge stop function at low VCC, Built-in high accuracy current detection amplifier, In standby mode, make output voltage setting resistor open to prevent inefficient current loss, Totem-pole type output for Pch MOS FET
2 to 4 cells	MB39A129	Built-in two constant current control loops, Built-in AC adapter detection function (ACOK terminal), Built-in output voltage control setting without external resistor, Adjustable output voltage with external resistor, Built-in two high accuracy current detection amplifiers, Built-in Charging Current Control setting without resistor, Adjustable charging current with external resistor, Support for frequency setting using an external resistor, (Frequency setting capacitor integrated), Built-in under voltage lockout protection, In standby mode, only AC adapter detection function is operated, Built-in VH regulator for reducing Qg loss of Pch MOS FET
	MB39A134	Built-in two constant current control loops, Built-in AC adapter detection function (ACOK terminal), Built-in output voltage control setting without external resistor, Adjustable output voltage with external resistor, Built-in two high accuracy current detection amplifiers, Built-in Charging Current Control setting without resistor, Adjustable charging current with external resistor, Support for frequency setting using an external resistor, (Frequency setting capacitor integrated), Built-in under voltage lockout protection, In standby mode, only AC adapter detection function is operated, Built-in VH regulator for reducing Qg loss of P-ch MOS FET

DC/DC converters for UMPC	Number of channels	Topology	Part number	Features
	6	Current Mode	MB39C308	For LPIA Platform VR, N/N Synchronous rectification, Integrated FET Driver for external MOSFETs(2ch), Integrated Switching MOSFETs(4ch), Preset Output Voltage, Soft start function/Soft stop function, Power good function, Various protection circuitry(SCP/OTP/OVP/OCP/UVLO/IVP)

(Continued)

Power Management Applications

Rechargeable Battery (Charge control)

Part number	Function	Power supply voltage (V)	Output voltage (V)	Precision (%)		Number of cells	Operating oscillator frequency (kHz) (Max.)	Solutions	Package			
				Ta = +25 °C	Ta = -30 to +85 °C				SSOP	TSSOP	QFN	
				MB3878	Charge control DC/DC converters				+7 to +25	4.2 V/cell	±0.8	±1.0
MB3887	+0.6 -0.4	±0.74 *	24P	-		-						
MB3888	Any voltage level		20P	-		-						
MB39A113	+8 to +25	4.2 V/cell	±0.5	±0.74 *		2 to 4	2000	2000	24P	-	-	-
MB39A118										-	-	28P
MB39A119		-	-	28P								
MB39A125		24P	-	28P								
MB39A129	4.145V/Cell, 3.75V/Cell, Any voltage level	±0.5	±0.7 *	2 to 4		2000	2000	24P	-	-		
○MB39A134	4.2V/Cell, 4.1V/Cell, Any voltage level	±0.5	±0.7 *	2 to 4	2000	2000	-	24P	-			

* : Ta = -10 to +85 °C

Package: P-plastic

○: New product

DC/DC converters for Ultra Mobile PC

Part number	Function	Input voltage (V)	Number of channels	Oscillator frequencies (kHz)	Output features				Solutions	Package
					Pin name	Preset Output Voltage (V)	FET	Drive or Output current (A) (Max)		PBGA
○MB39C308	DC/DC converters for LPIA Platform VR	+5.5 to +12.6	6	700 (Fix)	CH1	5	External	2	Down conversion	208P
					CH2	3.3		4.5		
					CH3	1.8/1.5	Integrated	2.7		
					CH4	0.9/0.75		1.5		
					CH5	1.5		2.5		
					CH6	1.05		3.5		

LPIA=Low Power Intel Architecture®

Package: P-plastic

○: New product

Power Management Applications

(Continued)

		Part number	Features	
Voltage detectors		MB3761	Wide operating voltage range, Easy addition of hysteresis characteristics	
Supply voltage monitoring applications	Watchdog timer			
		MB3771	Accurate supply voltage drop detection, External add-on allows detection of any desired voltage drop	
	Single system	MB3773	Watchdog timer Accurate supply voltage drop detection	
	Double systems	MB3793-27A MB3793-28A MB3793-30A MB3793-34A MB3793-37A MB3793-42 MB3793-45	Watchdog timer Accurate supply voltage drop detection	
Power management switches		MB3841	Low on-resistance switch	
		MB3842 MB3845	Low on-resistance switch	
LCD Panel	DC/DC	Gamma voltage generator	MB39C307A	6ch DC/DC + Gamma voltage generator Triangular frequency setting by external resistance Built-in soft-start circuit independent of loads Built-in rising sequence circuit Built-in thermal protection function Built-in 20ch./10-bit gamma voltage generate circuit Built-in VCOM voltage generate circuit
		2-ch. DC/DC + 2-ch. charge pump	MB39C313	DC/DC converters with P-ch. FET Soft-start, Sequence control, Short circuit protection, Over voltage protection, Over current protection, Over thermal protection

Power Management Applications

Voltage Detectors

Part number	Function	Power supply voltage (V)	Reference voltage (V) (Typ.)	Package	
				SOP	
MB3761	Voltage detector	+2.5 to +40	1.2	8P	

Package: P - Plastic

Supply Voltage Monitoring Applications

Part number	Function	Power supply voltage (V)	Detection voltage (V)	Reset certified voltage (V) (Typ.)	Package	
					SOP	SSOP
MB3771	Supply voltage monitoring applications	+3.5 to +18	Any voltage level in addition to 4.2 V	0.8	8P	-
MB3773	Supply voltage monitoring applications with watchdog timer	+3.5 to +16			8P	-
MB3793-27A ^{*1}	Supply voltage monitoring applications with dual watchdog timer systems	+4 (Max.)	2.7±0.07		8P	8P
MB3793-28A ^{*1}			2.8±0.07		8P	8P
MB3793-30A ^{*1}		+6 (Max.)	3.0±0.07		8P	8P
MB3793-34A ^{*1}			3.4±0.08		8P	(8P) ^{*2}
MB3793-37A ^{*1}			3.7±0.1		8P	(8P) ^{*2}
MB3793-42 ^{*1}			4.2±0.1		8P	(8P) ^{*2}
MB3793-45 ^{*1}		4.5±0.1	8P	8P		

^{*1}: Detection voltages of the MB3793 series are available in the range from 2.4 V to 4.9 V in 0.1 V increments. Package: P - Plastic
Consult with supplier.

^{*2}: () option

Switching Applications

Part number	Function	Power supply voltage (V) (Max.)	Number of channels	On-resistance (Ω)	Drive current (A) (Max.)	Package	
						SOP	SSOP
MB3841	Power management switch	5.5	1	0.045	2.0	8P	-
MB3842			2	0.1	0.6	-	20P
MB3845							

Package: P - Plastic

LCD Panel

Part number	Function	DC/DC Block						Gamma voltage generator block			Package
		Power supply voltage (V)	Number of channels	Reference voltage (V)	Precision (%)	Oscillation frequency (kHz)(Max)	Solution	Gamma voltage number of channel	VCOM voltage number of channel	DAC (bit)	BCC
○MB39C307A	DC/DC + Gamma voltage generator	+4.5 to +17	6	1 1.25	± 1.0	600	Step down 3ch Step up 2ch Invert 1ch	20	1	10	92P *

○: New product

Package: P - Plastic

*: With exposed pad

LCD Panel

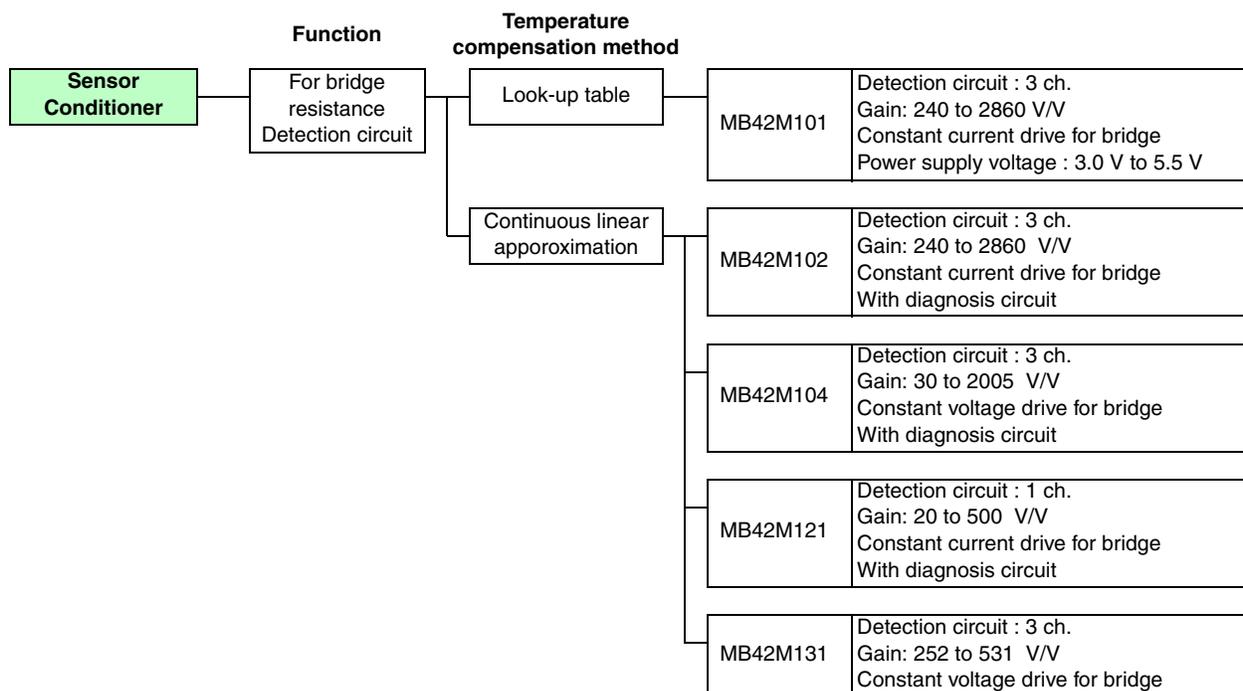
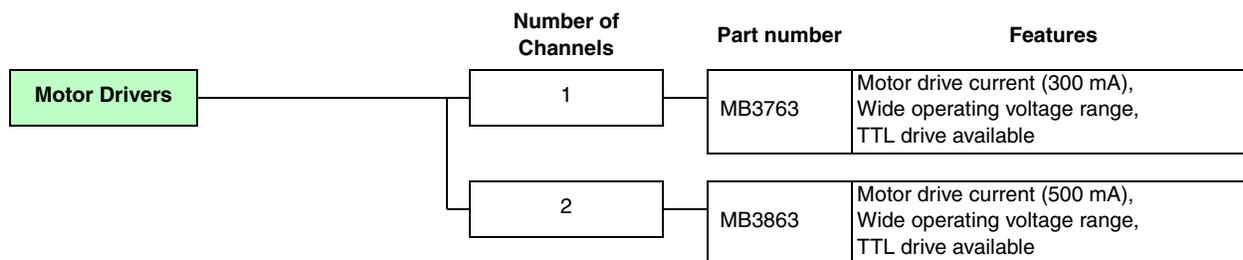
Part number	Function	Power supply voltage (V)	Number of channels	Reference voltage (V)	Precision	Oscillation frequency (kHz)	Solution	Package
								TSSOP
◎MB39C313	2ch. DC/DC + 2ch. charge pump	+8 to +14	4	1.213 1.146 0 1.213	± 1.0% ± 1.0% ± 36mV ± 1.0%	500/750	Step down Step up Invert charge pump Step up charge pump	28P *

◎: Now planning

Package: P - Plastic

*: With exposed pad

Motor Drivers/Sensor Conditioner



Motor Drivers/Sensor Conditioner

Motor Drivers

Part number	Function	Number of Channels	Output current (mA)	Power supply voltage (V)	Package
					SOP
MB3763	Reversible motor drivers	1	300	+4 to +18	8P
MB3863		2	500	+4 to +36	20P

Package: P - Plastic

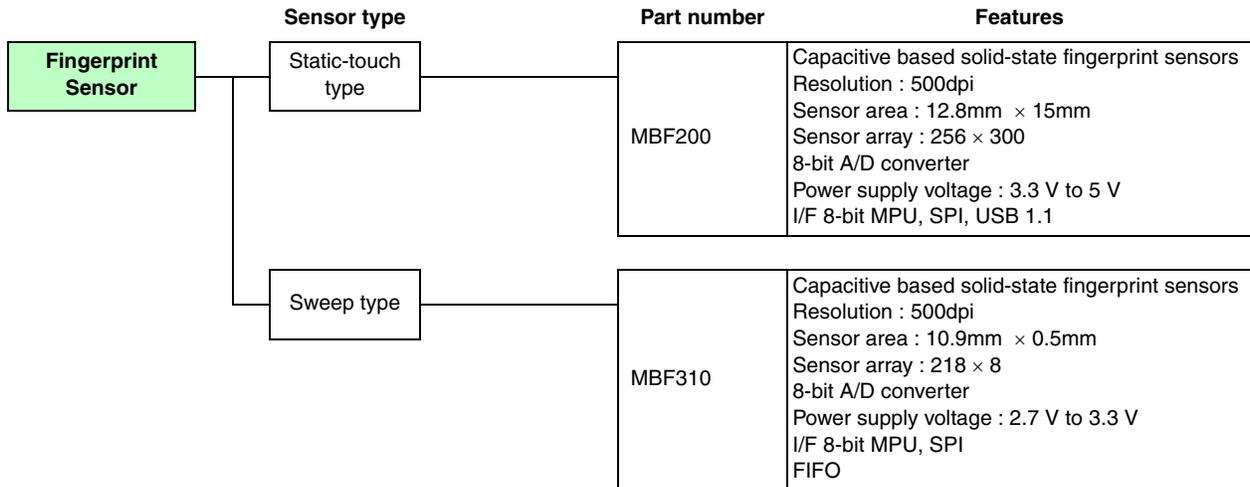
Sensor Conditioner

Part number	Function	Temperature compensation method	Number of detection circuits	Gain	Power supply voltage (V)	Others	Package	
							BCC	SSOP
MB42M101	For bridge resistance Detection circuit	Look-up table	3	240 to 2860 V/V	3.0 to 5.5	Digital compensation Constant current drive Built-in memory 1280 bits	32P	-
MB42M102	For bridge resistance Detection circuit	Continuous linear apporoximation	3	240 to 2860 V/V	4.5 to 5.5	Digital compensation Constant current drive Built-in memory 1280 bits Diagnosis circuit	40P	-
MB42M104	For bridge resistance Detection circuit	Continuous linear apporoximation	3	30 to 2005 V/V	4.5 to 5.5	Digital compensation Constant voltage drive Built-in memory 1280 bits Diagnosis circuit	40P	-
©MB42M121	For bridge resistance Detection circuit	Continuous linear apporoximation	1	20 to 500 V/V	2.7 to 3.6	Digital compensation Constant voltage drive Built-in memory 1280 bits Diagnosis circuit	-	20P
©MB42M131	For bridge resistance Detection circuit	Continuous linear apporoximation	3	252 to 531 V/V	2.7 to 3.6	Digital compensation Constant voltage drive	20P	-

©: Now planning

Package: P - Plastic

Fingerprint Sensor



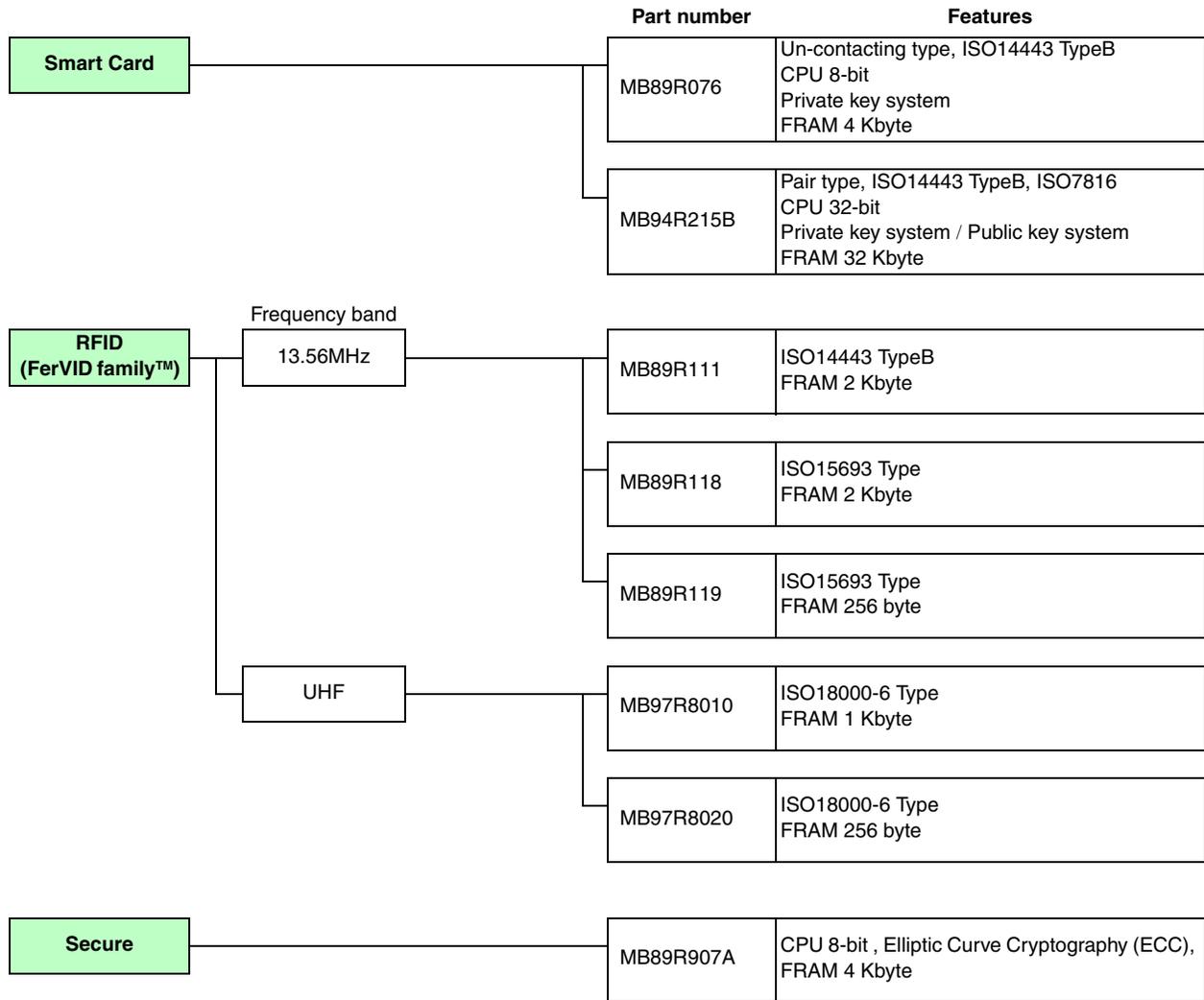
Fingerprint Sensor

■ Fingerprint Sensor

Part number	Resolution (dpi)	Sensor area (mm)	Sensor array (pixel)	Power supply voltage (V)	Interface	Others	Package	
							TSOP	FBGA
MBF200	500	12.8 × 15.0	256 × 300	3.3 to 5.0	8bit MPU SPI USB 1.1	-	80P	-
MBF310		10.9 × 0.5	218 × 8	2.7 to 3.3	8bit MPU SPI	FIFO	-	43P

Package: P - Plastic

Smart Card/RFID (FerVID family™) /Secure



Smart Card/RFID (FerVID family™) /Secure

Smart Card

Part number	Interface	CPU (bit)	FRAM (byte)	ROM (byte)	SRAM (byte)	Code Type	Shipment form
MB89R076	ISO14443 TypeB	8	4K	32K	512	DES	An exclusive package
MB94R215B	ISO14443 TypeB, ISO7816	32	32K	128K	8K	DES/RSA	An exclusive package

RFID (FerVID family™)

Part number	Frequency band	Interface	Transmission speed (Reader/Writer -> LSI)	Transmission speed (LSI -> Reader/Writer)	FRAM (byte)	Shipment form
MB89R111	13.56MHz	ISO14443 TypeB	106kbps, 212kbps	106kbps, 212kbps	2K	Wafer
MB89R118		ISO15693	26.48kbps (52.97kbps)	26.48kbps (52.97kbps)	2K	Wafer (With a golden Bump)
MB89R119		ISO15693	26.48kbps (52.97kbps)	26.48kbps (52.97kbps)	256	Wafer (With a golden Bump)
○MB97R8010	UHF	ISO18000-6 TypeB	10kbps, 40kbps	10kbps, 40kbps	1K	Wafer (With a golden Bump)
○MB97R8020		ISO18000-6 TypeB	10kbps, 40kbps	10kbps, 40kbps	256	Wafer (With a golden Bump)

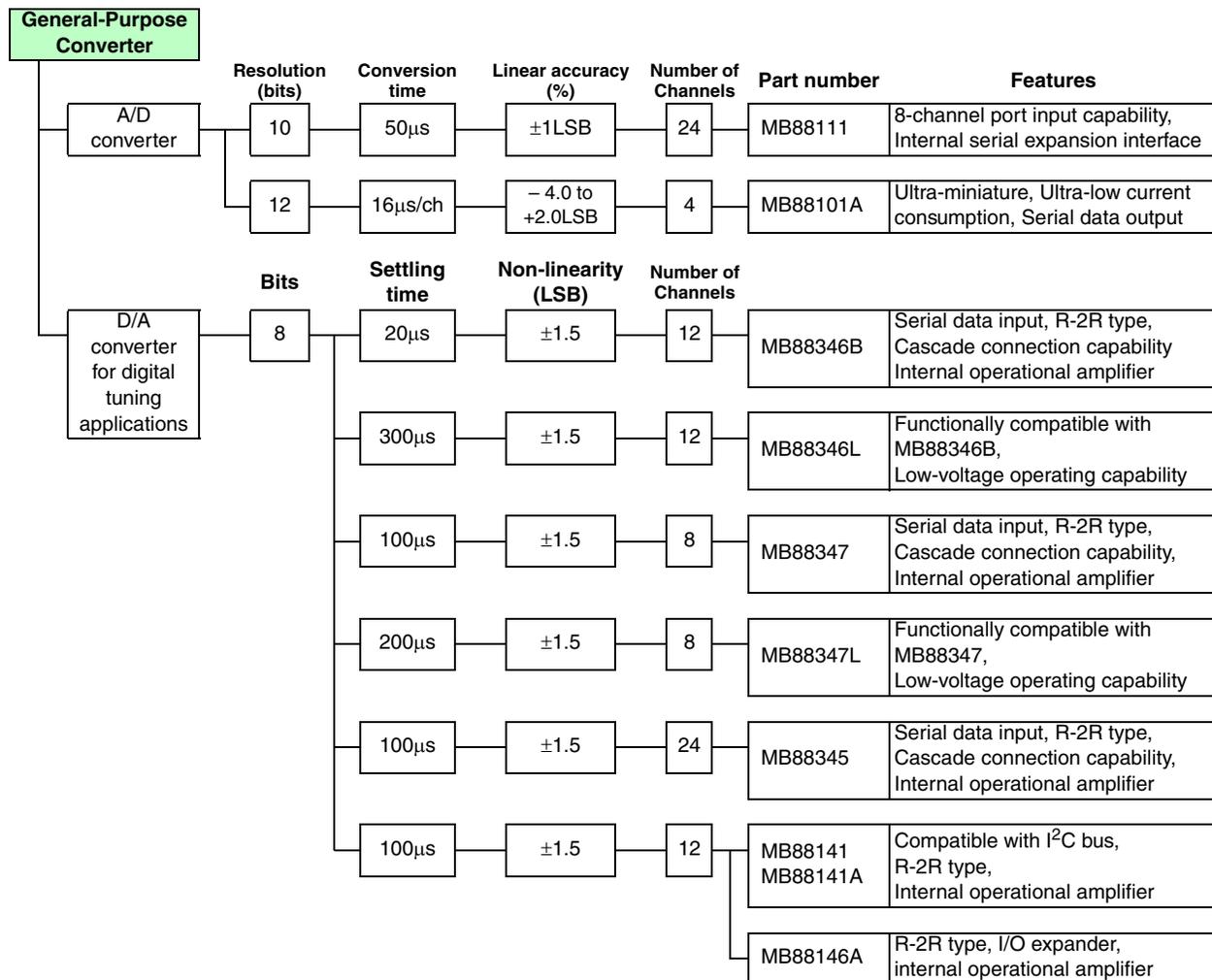
○: New product

Secure

Part number	CPU (bit)	FRAM (byte)	ROM (byte)	SRAM (byte)	Code Type	Power supply voltage (V)	Package
							QFP
MB89R907A	8	4K	32K	1K	Elliptic Curve Cryptography (ECC)	+5 ± 5%	48P

Package: P - Plastic

General-Purpose Converter



General-Purpose Converter

General-Purpose Converter

A/D Converter

Part number	Function	Conversion method	Conversion time ($\mu\text{s}/\text{ch}$) (Max.)	Linearity error (%) (Max.)	Power supply voltage (V)	Package				
						DIP	SOP	SSOP	QFP	SH-DIP
MB88111	24-ch 10-bit A/D converter	Successive approximation	50	± 1 LSB	+3.5 to +5.5	–	–	–	44P	48P
MB88101A	4-ch 12-bit A/D converter		16 (at 5 V $\pm 10\%$)	-4.0 to +2.0 LSB	+3.3 to +5.5	16P	16P	16P	–	–

Packages: P - Plastic

D/A Converter for Digital Tuning Applications

Part number	Function	Settling time (μs) (Max.)	Power consumption (mW) (Typ.)	Non-linearity error (LSB)	Power supply voltage (V)	Package			
						DIP	SOP	SSOP	QFP
MB88346B	12-ch 8-bit D/A converter (internal operational amplifier)	20	14	± 1.5	+5 $\pm 10\%$	20P	20P	20P	–
MB88346L	12-ch 8-bit D/A converter (internal operational amplifier, low voltage operation)	300	5		+2.7 to +3.6	20P	20P	20P	–
MB88347	8-ch 8-bit D/A converter (internal operational amplifier)	100	9		+5 $\pm 10\%$	16P	16P	16P	–
MB88347L	8-ch 8-bit D/A converter (internal operational amplifier, low voltage operation)	200	4.2		+2.7 to +3.6	16P	16P	16P	–
MB88345	24-ch 8-bit D/A converter (internal operational amplifier)	100	27		+5 $\pm 10\%$	–	–	–	32P
MB88141 *	12-ch 8-bit D/A converter (compatible with I ² C bus, internal operational amplifier)	100	15			24P	24P	24P	–
MB88141A *									
MB88146A	12-ch 8-bit D/A converter (I/O expander, internal operational amplifier)		14.5		Digital:+2.7 to +5.5 Analog:+5 $\pm 10\%$	24P	–	24P	–

Package: P - Plastic

* "Purchase of Fujitsu Microelectronics I²C components conveys a license under the Philips I²C Patent Rights to use these components in an I²C system, provided that the system conforms to the I²C Standard Specification as defined by Philips."

Spread Spectrum Clock Generator

Spread Spectrum Clock Generator	Efficiency of multiply	Part number	Features
	$\times 1/2, \times 1,$ $\times 2, \times 4,$ $\times 8$	MB88151A	Input frequency : 16.6 to 33.4 MHz Modulation type : center/down (selection) Modulation sensitivity: -1.0%, -3.0%, $\pm 0.5%$, $\pm 1.5%$ (down/center) Power supply voltage : 3.3 V \pm 0.3 V Power down function / modulation enable function ** With multiply circuit, SOP-8 pin **: The Input frequency wide range, the modulation type and the modulation sensitivity are different to the option.
	$\times 1$	MB88152A	Input frequency : 16.6 to 134 MHz ** Modulation type : center/down * Modulation sensitivity: -1.0%, -3.0%, $\pm 0.5%$, $\pm 1.5%$, no modulation ** (down/center) Power supply voltage : 3.3 V \pm 0.3 V Input frequency wide range version, SOP-8 pin **: The Input frequency wide range, the modulation type and the modulation sensitivity are different to the option.
		MB88153A	Input frequency : 16.6 to 134 MHz Modulation type : center/down ** Modulation sensitivity: -1.0%, -3.0%, $\pm 0.5%$, $\pm 1.5%$, no modulation ** (down/center) Power supply voltage : 3.3 V \pm 0.3 V Power down function, external clock input only, SOP-8 pin **: The modulation type and the modulation sensitivity are different to the option.
		MB88154A	Input frequency : 16.6 to 67 MHz ** Modulation type : center/down ** Modulation sensitivity: -1.0%, -2.0%, -3.0%, $\pm 0.5%$, $\pm 1.0%$, $\pm 1.5%$, no modulation ** (down/center) Power supply voltage : 3.3 V \pm 0.3 V REF output, SOP-8 pin **: The Input frequency wide range, the modulation type and the modulation sensitivity are different to the option.

(Continued)

Spread Spectrum Clock Generator

■ Spread Spectrum Clock Generator

Part number	Function	Power supply voltage	Input frequency (MHz)	Efficiency of multiply	Output frequency (MHz)	Modulation Type	Modulation sensitivity	Other	Package			
									SOP			
MB88151A-100	EMI noise reduction PLL (SSCG)	3.3 ± 0.3	16.6 to 33.4	× 1	16.6 to 33.4	Down or center (selection)	-1.0%, -3.0% (down) ±0.5%, ±1.5% (center) no modulation (no modulation setting is no PD product)	PD function disable	8P			
MB88151A-101								PD function enable				
MB88151A-200				× 2	33.2 to 66.8			PD function disable				
MB88151A-201								PD function enable				
MB88151A-400				× 4	66.4 to 133.6			PD function disable				
MB88151A-401								PD function enable				
MB88151A-500				× 1/2	8.3 to 16.7			PD function disable				
MB88151A-501								PD function enable				
MB88151A-800			× 8	66.4 to 133.6	PD function disable							
MB88151A-801					PD function enable							
MB88152A-100			EMI noise reduction PLL (SSCG)	3.3 ± 0.3	16.6 to 40 33 to 67 40 to 80 66 to 134	× 1	16.6 to 40 33 to 67 40 to 80 66 to 134	Down		-1.0%, -3.0%	-	8P
MB88152A-110								Center		±0.5%, ±1.5%		
MB88152A-101	16.6 to 40 33 to 67	× 1			16.6 to 40 33 to 67	Down	-1.0%, -3.0% no modulation					
MB88152A-111						Center	±0.5%, ±1.5% no modulation					
MB88152A-102	40 to 80 66 to 134	× 1			40 to 80 66 to 134	Down	-1.0%, -3.0% no modulation					
MB88152A-112						Center	±0.5%, ±1.5% no modulation					
MB88153A-100	16.6 to 40 66 to 134 33 to 67 40 to 80	× 1			16.6 to 40 66 to 134 33 to 67 40 to 80	Down	-1.0%, no modulation	PD function enable	8P			
MB88153A-101							-3.0%, no modulation					
MB88153A-110						Center	±0.5%, no modulation					
MB88153A-111							±1.5%, no modulation					
MB88154A-102	33 to 67	× 1			33 to 67	Down	-1.0%, -2.0%, 3.0%, no modulation	REF output enable	8P			
MB88154A-103	16.6 to 40				16.6 to 40							
MB88154A-112	33 to 67		33 to 67	Center	±0.5%, ±1.0%, ±1.5%, no modulation							
MB88154A-113	16.6 to 40		16.6 to 40									

Package: P - Plastic
(Continued)

ASSP

Spread Spectrum Clock Generator

(Continued)

Efficiency of multiply	Part number	Features
× 1, × 4	MB88155	Input frequency : 12.5 to 50 MHz (× 1) * 12.5 to 20 MHz (× 4) Modulation type : center/down * Modulation sensitivity: -1.0%, -2.0%, ±0.5%, ±1.0%, no modulation * (down/center) Power supply voltage : 3.3 V ± 0.3 V Power down function / modulation enable function TSSOP-8 pin
*: The Input frequency wide range, the modulation type and the modulation sensitivity are different to the option.		
× 1, × 2, × 4 (selection)	MB88156	Input frequency : 12.5 to 50 MHz Modulation type : center/down (selection) Modulation sensitivity: -1.0%, -2.0%, -3.0%, ±0.5%, ±1.5%, no modulation (down/center) Power supply voltage : 3.3 V ± 0.3 V REF output/none With multiply circuit, BCC-16 pin
× 1, × 2, (selection)	MB88161	Input frequency : 20 to 28 MHz Modulation type : center/down (selection) Modulation sensitivity: -1.0%, -2.0%, -4.0%, ±0.5%, ±1.0%, ±2.0%, no modulation (down/center) Power supply voltage : 3.3 V ± 0.3 V Power down function, BCC-18 pin
× 1, × 4, (selection)	MB88162	Input frequency : 12 to 28 MHz Modulation type : center/down (selection) Modulation sensitivity: -1.0%, -2.0%, -4.0%, ±0.5%, ±1.0%, ±2.0%, no modulation (down/center) Power supply voltage : 3.3 V ± 0.3 V Power down function, BCC-18 pin
× 1, × 2, × 4	MB88163 (Under development)	Input frequency : 12.5 to 42 MHz * Modulation type : center Modulation sensitivity: ±0.25%, ±0.5%, ±1.0%, no modulation (center) Power supply voltage : 1.8 V ± 0.15 V Output enable function * TSSOP-8 pin/BCC-6 pin
*: The Input frequency wide range, modulation sensitivity and output enable function are different to the option.		
× 1/2 or more (MASK option)	MB88181	Input frequency : 16 to 32 MHz Modulation type : center Modulation sensitivity: ±0.5%, ±1.0%, ±1.5%, ±2.0%, no modulation (center) Power supply voltage : 3.3 V ± 0.3 V Clock output 8(Max.), power down function, TSSOP-20 pin
*: The efficiency of multiply and the output mode can be arbitrarily set by the mask option.		

Spread Spectrum Clock Generator

(Continued)

Part number	Function	Power supply voltage (V)	Input frequency (MHz)	Efficiency of multiply	Output frequency (MHz)	Modulation Type	Modulation sensitivity	Other	Package			
									TSSOP	BCC		
MB88155-100	EMI noise reduction PLL (SSCG)	3.3 ± 0.3	12.5 to 25	× 1	12.5 to 25	Down	-1.0%, -2.0% no modulation	PD function disable	8P	-		
MB88155-101			25 to 50		25 to 50			PD function enable				
MB88155-102			12.5 to 25		12.5 to 25			Center			±0.5%, ±1.0% no modulation	PD function disable
MB88155-103			25 to 50		25 to 50							PD function enable
MB88155-110			12.5 to 25		12.5 to 25	Down	-1.0%, -2.0% no modulation	PD function disable				
MB88155-111			25 to 50		25 to 50			PD function enable				
MB88155-112			12.5 to 25		12.5 to 25			Center			±0.5%, ±1.0%	PD function disable
MB88155-113			25 to 50		25 to 50							PD function enable
MB88155-400			12.5 to 20	× 4	50 to 80	Down	-1.0%, -2.0% no modulation	PD function disable				
MB88155-402								Center			±0.5%, ±1.0% no modulation	PD function enable
MB88155-410												±0.5%, ±1.0%
MB88155-412								PD function enable				
MB88156-000			20 to 28 (× 1) 14 to 40 (× 2)	× 1, × 2, (selection)	20 to 28 (× 1) 28 to 80 (× 2)	Down/Center (selection)	-1.0%, -2.0%, ±0.5%, ±1.0%, no modulation	REF output enable			-	16P
MB88156-001								REF output disable				
MB88161	12 to 28 (× 1) 20 to 42 (× 4)	× 1, × 4, (selection)	12 to 28 (× 1) 80 to 168 (× 4)	Down/Center (selectable)	-1.0%, -2.0%, -4.0%, ±0.5%, ±1.0%, ±2.0%, no modulation	PD function enable	-	18P				
MB88162	12 to 28 (× 1) 20 to 42 (× 4)	× 1, × 4, (selectable)	12 to 28 (× 1) 80 to 168 (× 4)			PD function enable	-	18P				
© MB88163	1.8 ± 0.15	20 to 42	12.5 to 26	× 1	12.5 to 26	Center	±0.5%, no modulation	-	8P	-		
© MB88163-100								20 to 42			±0.25%, ±0.5%, ±1.0%, no modulation	OE function enable
© MB88163-200								× 2			40 to 84	
© MB88163-400								× 4			80 to 168	
© MB88163-500								12.5 to 26			× 1	12.5 to 26
MB88181	3.3 ± 0.3	16 to 32	× 1/2 or more *	8 to 166	Center	±0.5%, ±1.0%, ±1.5%, ±2.0%, no modulation	PD function enable, Clock output 8(Max.)	20P	-			

*: The efficiency of multiply and the output mode can be arbitrarily set by the mask option.

Package: P - Plastic

©: Now planning

Spread Spectrum Clock Generator

SSCG Simple Evaluation Board

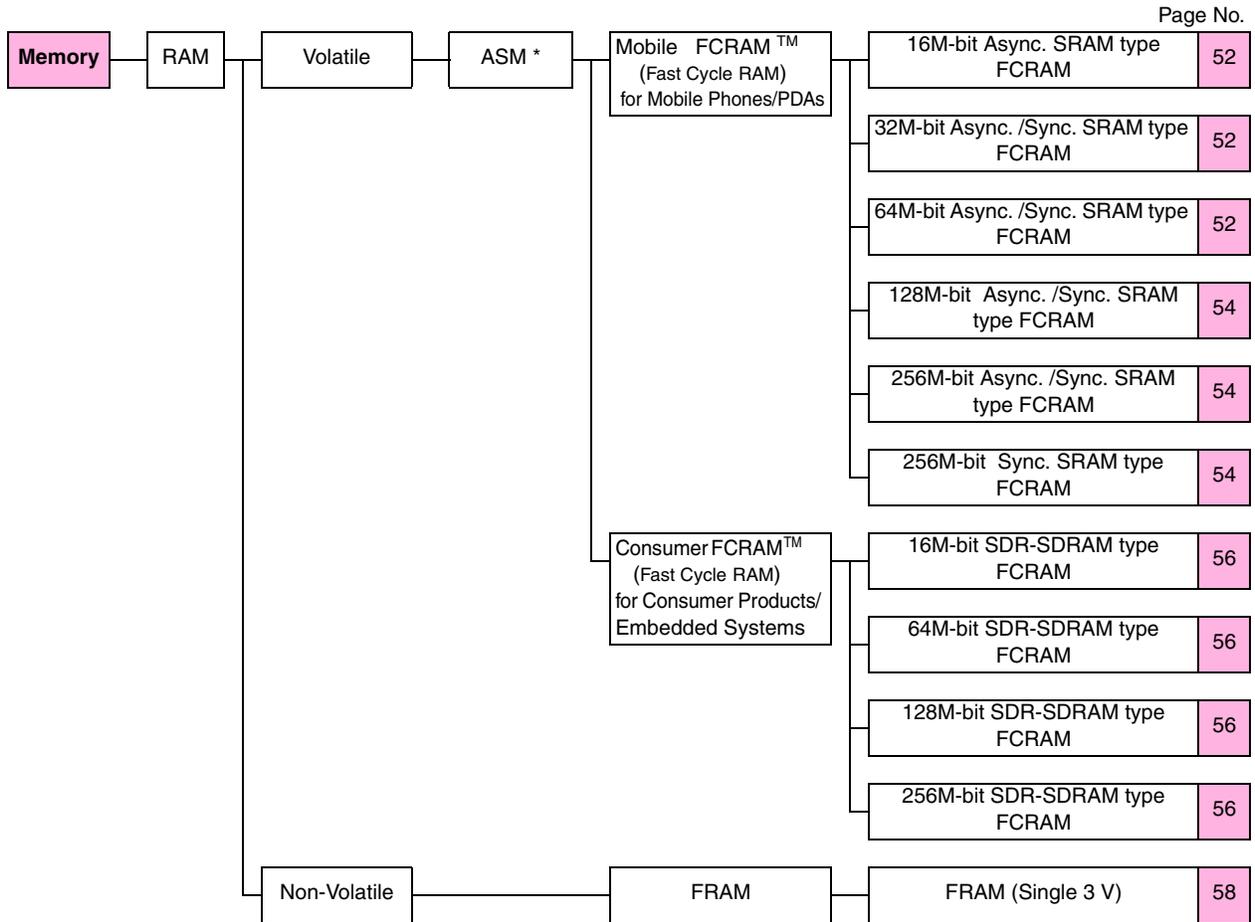
Part number		Remarks
MB88151A	MB88151AEB01-100	MB88151A-100 mounted
	MB88151AEB01-101	MB88151A-101 mounted
	MB88151AEB01-200	MB88151A-200 mounted
	MB88151AEB01-201	MB88151A-201 mounted
	MB88151AEB01-400	MB88151A-400 mounted
	MB88151AEB01-401	MB88151A-401 mounted
	MB88151AEB01-500	MB88151A-500 mounted
	MB88151AEB01-501	MB88151A-501 mounted
	MB88151AEB01-800	MB88151A-800 mounted
	MB88151AEB01-801	MB88151A-801 mounted
MB88152A	MB88152AEB01-100	MB88152A-100 mounted
	MB88152AEB01-110	MB88152A-110 mounted
	MB88152AEB01-101	MB88152A-101 mounted
	MB88152AEB01-111	MB88152A-111 mounted
	MB88152AEB01-102	MB88152A-102 mounted
	MB88152AEB01-112	MB88152A-112 mounted
MB88153A	MB88153AEB01-100	MB88153A-100 mounted
	MB88153AEB01-101	MB88153A-101 mounted
	MB88153AEB01-110	MB88153A-110 mounted
	MB88153AEB01-111	MB88153A-111 mounted
MB88154A	MB88154AEB01-102	MB88154A-102 mounted
	MB88154AEB01-103	MB88154A-103 mounted
	MB88154AEB01-112	MB88154A-112 mounted
	MB88154AEB01-113	MB88154A-113 mounted
MB88155	MB88155EB01-100	MB88155-100 mounted
	MB88155EB01-101	MB88155-101 mounted
	MB88155EB01-102	MB88155-102 mounted
	MB88155EB01-103	MB88155-103 mounted
	MB88155EB01-110	MB88155-110 mounted
	MB88155EB01-111	MB88155-111 mounted
	MB88155EB01-112	MB88155-112 mounted
	MB88155EB01-113	MB88155-113 mounted
	MB88155EB01-400	MB88155-400 mounted
	MB88155EB01-402	MB88155-402 mounted
MB88156	MB88156EB01-BC16-000	MB88156-000 mounted
	MB88156EB01-BC16-001	MB88156-001 mounted
MB88161	MB88161EB01	MB88161 mounted
MB88162	MB88162EB01	MB88162 mounted
MB88163	⊙MB88163EB01	MB88163 mounted
	⊙MB88163EB01	MB88163-100 mounted
	⊙MB88163-200EB02	MB88163-200 mounted
	⊙MB88163-400EB02	MB88163-400 mounted
	⊙MB88163-500EB02	MB88163-500 mounted

An oscillation vibrator, oscillation stable capacity, and a power supply line are required.

⊙: Now planning

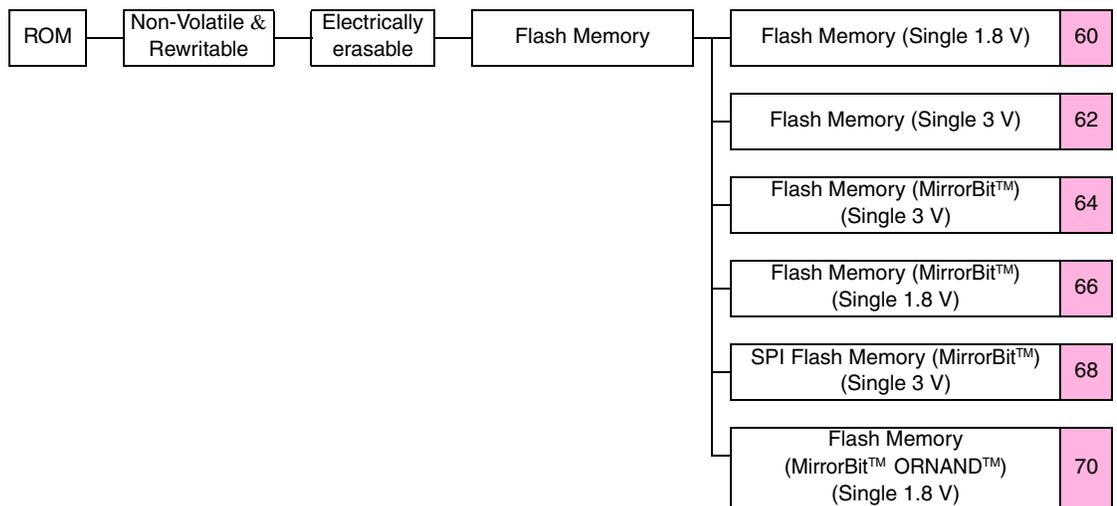
Memory Product Line-up

Memory Product Line-up



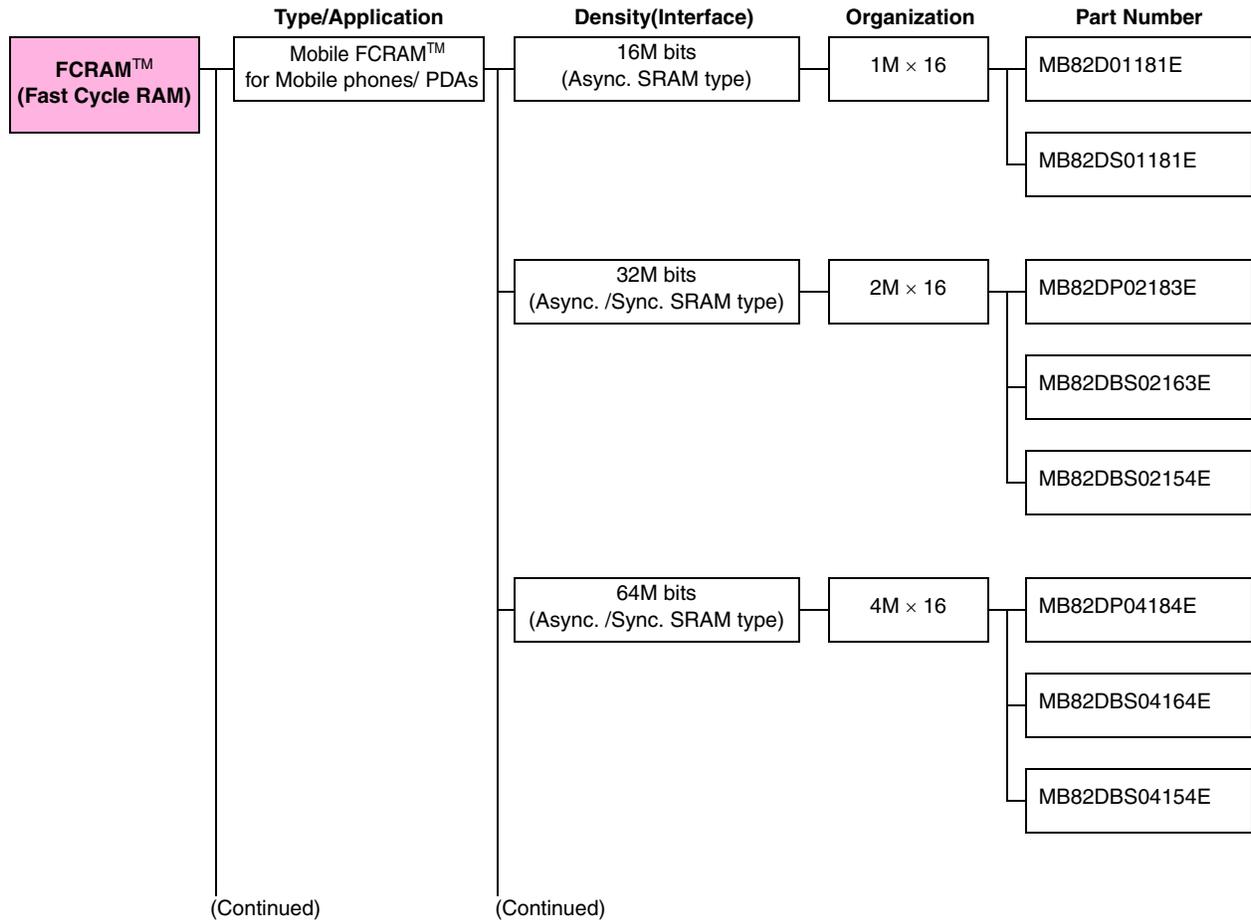
* : ASM =Application Specific Memory
FCRAM is a trademark of Fujitsu Microelectronics Limited.

SPANSION™ Products



MirrorBit is a trademark of Spansion Inc.
ORNAND is a trademark of Spansion Inc.

FCRAM™ (Fast Cycle RAM) (1)



FCRAM is a trademark of Fujitsu Microelectronics Limited.

FCRAM™ (Fast Cycle RAM) (1)

■ Mobile FCRAM™ (Fast Cycle RAM)

• 16M-bit Async. SRAM Type FCRAM

Organization (W × b)	Part Number	Initial Access Time Max. (ns)	Page Mode Access Time Max. (ns)	Burst Mode Frequency Max. (MHz)	Burst Clock Access Time Max. (ns)	Supply Current Max.			Supply Voltage (V)
						Operating (mA)	Standby (μA)	Power Down (μA)	
1M × 16	MB82D01181E-60L *1	60	N/A	N/A	N/A	20	100 *3	10	2.3 to 3.5
	MB82DS01181E-70L *2	70	N/A	N/A	N/A	20	100	10	1.7 to 1.95

*1: Shipping form: Chip, wafer, 48-pin FBGA package (SRAM compatible pinout)

*2: Shipping form: Chip, wafer

Package support for mass production is T.B.D.

*3: At $V_{DD} \leq 3.1V$

• 32M-bit Async. /Sync. SRAM Type FCRAM

*1, *2, *3

Organization (W × b)	Part Number	Initial Access Time Max. (ns) *4	Page Mode Access Time Max. (ns)	Burst Mode Frequency Max. (MHz)	Burst Clock Access Time Max. (ns)	Supply Current Max.			Supply Voltage (V)
						Operating (mA)	Standby (μA)	Power Down (μA)	
2M × 16	MB82DP02183E-65L	65	20	N/A	N/A	30	120	10	2.6 to 3.1
	MB82DBS02163E-70L	70	20	83	8 *5	30	120	10	1.7 to 1.95
	MB82DBS02154E-70L	70	N/A	104	7 *6	30	120	10	1.7 to 1.95

*1: Compliant with COSMORAM spec

*2: MB82DP02183E : with Page mode

MB82DBS02163E : with SDR Burst mode & Page mode

MB82DBS02154E : with SDR Burst mode & Multiplexed Address and Data Bus

*3: Shipping form: Chip, wafer, 71-pin FBGA package

*4: At asynchronous operation

*5: At RL = 5, 6

*6: At RL = 7

• 64M-bit Async. /Sync. SRAM Type FCRAM

*1, *2, *3

Organization (W × b)	Part Number	Initial Access Time Max. (ns) *4	Page Mode Access Time Max. (ns)	Burst Mode Frequency Max. (MHz)	Burst Clock Access Time Max. (ns)	Supply Current Max.			Supply Voltage (V)
						Operating (mA)	Standby (μA)	Power Down (μA)	
4M × 16	MB82DP04184E-65L	65	20	N/A	N/A	40	200	10	2.6 to 3.1
	MB82DBS04164E-70L	70	20	104	7 *5	40	200	10	1.7 to 1.95
	MB82DBS04154E-70L	70	N/A	104	7 *5	40	200	10	1.7 to 1.95

*1: Compliant with COSMORAM spec

*2: MB82DP04184E : with Page mode

MB82DBS04164E : with SDR Burst mode & Page mode

MB82DBS04154E : with SDR Burst mode & Multiplexed Address and Data Bus

*3: Shipping form: Chip, wafer

Package (71-pin FBGA) support for mass production is T.B.D.

*4: At asynchronous operation

*5: At RL = 6, 7

FCRAM™ (Fast Cycle RAM) (2)

(Continued)

Type/Application	Density(Interface)	Organization	Part Number
Mobile FCRAM™ for Mobile phones/PDAs	128M bits (Async. /Sync. SRAM type)	8M × 16	MB82DBS08164C
			MB82DBS08164D
	256M bits (Async. /Sync. SRAM type)	16M × 16	MB82DBS16164A
		8M × 32	MB82DBS08314A
	256M bits (Sync. SRAM type)	8M × 32	MB82DDS08314A

(Continued)

FCRAM is a trademark of Fujitsu Microelectronics Limited.

FCRAM™ (Fast Cycle RAM) (2)

• 128M-bit Async. /Sync. SRAM Type FCRAM

*1, *2

Organization (W × b)	Part Number	Initial Access Time Max. (ns) *3	Page Mode Access Time Max. (ns)	Burst Mode Frequency Max. (MHz)	Burst Clock Access Time Max. (ns)	Supply Current Max.			Supply Voltage (V)
						Operating (mA)	Standby (μA)	Power Down (μA)	
8M × 16	MB82DBS08164C-70L	70	N/A	104	6 *4	40	300	10	1.7 to 1.95
	○ MB82DBS08164D-70L	70	N/A	104	6 *4	35 *5	200	10	1.7 to 1.95

○ : New Product

*1: Compliant with COSMORAM spec, with SDR Burst mode

*2: Shipping form: Chip, wafer

Package support for mass production is T.B.D.

*3: At asynchronous operation

*4: At RL = 6, 7

*5: $T_A \leq +40^\circ\text{C}$

• 256M-bit Async. /Sync. SRAM Type FCRAM

*1, *2

Organization (W × b)	Part Number	Initial Access Time Max. (ns) *3	Page Mode Access Time Max. (ns)	Burst Mode Frequency Max. (MHz)	Burst Clock Access Time Max. (ns)	Supply Current Max.			Supply Voltage (V)
						Operating (mA)	Standby (μA)	Power Down (μA)	
16M × 16	MB82DBS16164A-80L	80	N/A	100	7 *4	40	250 *5	10	1.7 to 1.95
8M × 32	MB82DBS08314A-80L	80	N/A	100	7 *4	40	250 *5	10	1.7 to 1.95

*1: Compliant with COSMORAM spec, with SDR Burst mode

*2: Shipping form: Chip, wafer

Package(115-pin FBGA) support for mass production is T.B.D.

*3: At asynchronous operation

*4: At RL = 7, 8

*5: $T_A \leq +40^\circ\text{C}$

• 256M-bit Sync. SRAM Type FCRAM

*1, *2

Organization (W × b)	Part Number	Initial Access Time Max. (ns) *3	Page Mode Access Time Max. (ns)	Burst Mode Frequency Max. (MHz)	Burst Clock Access Time Max. (ns)	Supply Current Max.			Supply Voltage (V)
						Operating (mA)	Standby (μA)	Power Down (μA)	
8M × 32	MB82DDS08314A-75L	45	N/A	135	6 *4	40	250 *5	10	1.75 to 1.95

*1: Compliant with COSMORAM spec, with DDR Burst mode & Multiplexed Address and Data Bus

*2: Shipping form: Chip, wafer

Package(115-pin FBGA) support for mass production is T.B.D.

*3: At Burst mode

*4: Data access time from CLK, $\overline{\text{CLK}}$

*5: $T_A \leq +40^\circ\text{C}$

FCRAM™ (Fast Cycle RAM) (3)

(Continued)

Type/Application	Density (Interface)	Organization	Part Number
Consumer FCRAM™ for Consumer Products/ Embedded Systems	16M bits (SDR-SDRAM type)	2 × 512K × 16	MB81ES171625 MB81ES171625-X
		2 × 256K × 32	MB81ES173225 MB81ES173225-X
	64M bits (SDR-SDRAM type)	4 × 1M × 16	MB81ES641645A
	128M bits (SDR-SDRAM type)	4 × 1M × 32	MB81ES123245
	256M bits (SDR-SDRAM type)	4 × 2M × 32	MB81ES253245

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FCRAM™ (Fast Cycle RAM) (3)

■ Consumer FCRAM™ (Fast Cycle RAM)

● 16M-bit SDR-SDRAM Type FCRAM

*1, *2

Organization (Bank × W × b)	Part Number	Clock Frequency Max. (MHz)	Clock Period Min. (ns)	Access Time Max. (ns) *4	Supply Current Max. *5		Supply Voltage (V)
					Operating (mA)	Standby (mA)	
2 × 512K × 16	MB81ES171625-12	85	11.7	10.2	30	1	1.65 to 1.95
	MB81ES171625-15	66.7	15	12	30	1	1.65 to 1.95
	MB81ES171625-15-X *3	66.7	15	12	30	1	1.65 to 1.95
2 × 256K × 32	MB81ES173225-12	85	11.7	10.2	30	1	1.65 to 1.95
	MB81ES173225-15	66.7	15	12	30	1	1.65 to 1.95
	MB81ES173225-15-X *3	66.7	15	12	30	1	1.65 to 1.95

*1: Single Data Rate SDRAM Interface

*2: Shipping form: Chip, wafer

*3: Extended operating temperature

*4: Access Time = t_{AC}

*5: Operating current is I_{DD1} (1 bank active) and Standby current is I_{DD2P} (Power down mode)

● 64M-bit SDR-SDRAM Type FCRAM

*1, *2

Organization (Bank × W × b)	Part Number	Clock Frequency Max. (MHz)	Clock Period Min. (ns)	Access Time Max. (ns) *3	Supply Current Max.		Supply Voltage (V)
					Operating (mA)	Standby (mA)	
4 × 1M × 16	○ MB81ES641645A-07	135	7.4	6.5	T.B.D.	T.B.D.	1.7 to 1.95

○ : New Product

*1: Single Data Rate SDRAM Interface

*2: Shipping form: Chip, wafer, 54-pin FBGA package

*3: Access Time = t_{AC}

● 128M-bit SDR-SDRAM Type FCRAM

*1, *2

Organization (Bank × W × b)	Part Number	Clock Frequency Max. (MHz)	Clock Period Min. (ns)	Access Time Max. (ns) *3	Supply Current Max. *4		Supply Voltage (V)
					Operating (mA)	Standby (mA)	
4 × 1M × 32	MB81ES123245-10	108	9.2	7	*5	0.5	1.7 to 1.9

*1: Single Data Rate SDRAM Interface

*2: Shipping form: Chip, wafer

*3: Access Time = t_{AC}

*4: Operating current is I_{DD1} (1 bank active) and Standby current is I_{DD2P} (Power down mode)

*5: 60 (256 page length) , 45 (128 page Length) , 35 (64 page length)

● 256M-bit SDR-SDRAM Type FCRAM

*1, *2

Organization (Bank × W × b)	Part Number	Clock Frequency Max. (MHz)	Clock Period Min. (ns)	Access Time Max. (ns) *3	Supply Current Max.		Supply Voltage (V)
					Operating (mA)	Standby (mA)	
4 × 2M × 32	◎ MB81ES253245	166	6	6	T.B.D.	T.B.D.	1.7 to 1.95

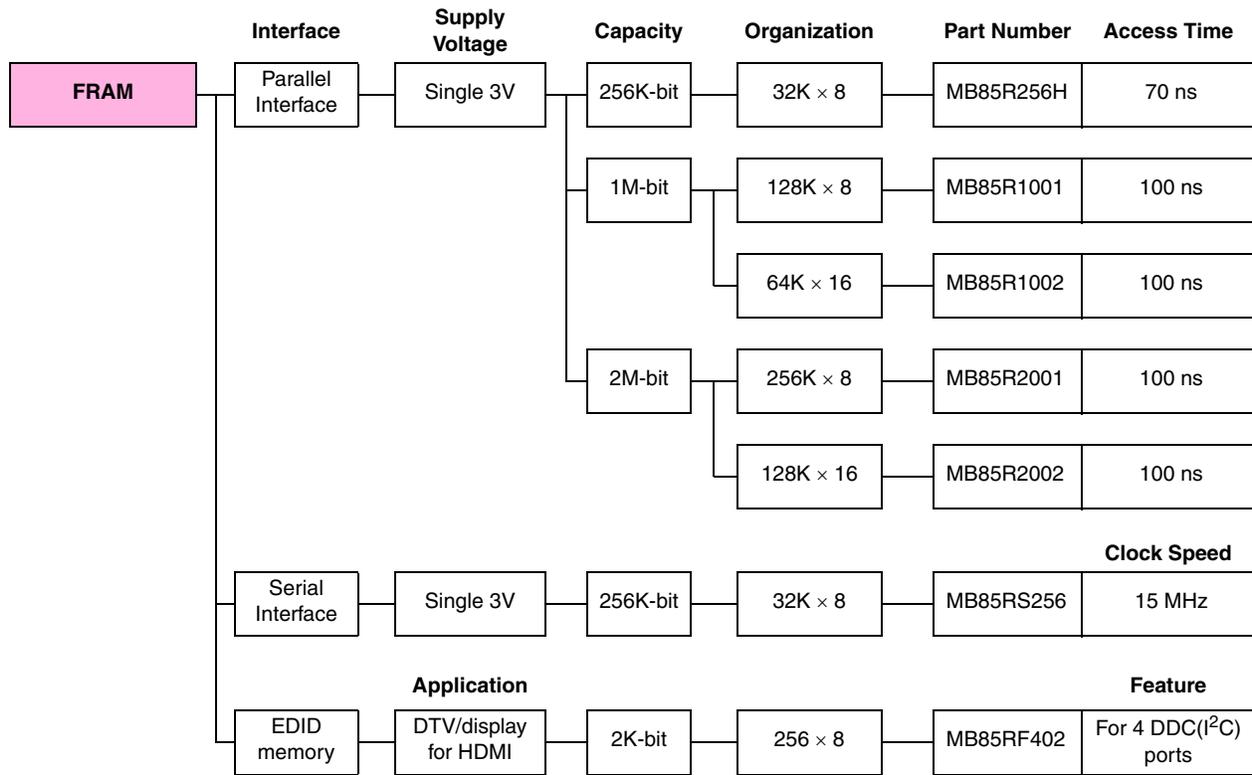
◎: Under development

*1: Single Data Rate SDRAM Interface

*2: Shipping form: Chip, wafer

*3: Access Time = t_{AC}

FRAM (Ferroelectric RAM)



FRAM (Ferroelectric RAM)

FRAM

Interface	Organization (W × b)	Part Number	Access Time Max. (ns)	Cycle Time Min. (ns)	Clock Speed Max. (MHz)	V _{CC} Current		Supply Voltage (V)	Operating Temperature Range T _A (°C)	Packages		
						Operating (mA)	Standby (μA)			SOP	TSOP	FBGA
Parallel	32K × 8	MB85R256H	70	150	-	5	5	2.7 to 3.6	-40 to +85	28P	28P	-
Parallel	128K × 8	MB85R1001	100	150	-	10	10	3.0 to 3.6	-20 to +85	-	48P	-
Parallel	64K × 16	MB85R1002	100	150	-	10	10	3.0 to 3.6	-20 to +85	-	48P	48P
Parallel	256K × 8	MB85R2001	100	150	-	10	10	3.0 to 3.6	-20 to +85	-	48P	-
Parallel	128K × 16	MB85R2002	100	150	-	10	10	3.0 to 3.6	-20 to +85	-	48P	-
Serial	32K × 8	MB85RS256	-	-	15	5	3	3.0 to 3.6	-20 to +85	8P	-	-

Package : P – Plastic

EDID memory

Part Number	Memory	Organization (W × b)	Interface	Supply Voltage (V)	Packages
					TSSOP
○ MB85RF402	FRAM	256 × 8	For 4 DDC(I ² C) ports	3.8 to 5.5	16P

○ : New released.

Package : P – Plastic

Flash Memory (Single 1.8V)

SPANSION™ Products

	Supply Voltage	Capacity	Organization	Part Number	Variation	Access Time	Remarks
Flash Memory	Single 1.8V	8 M bit	1 M × 8 512K × 16	S29AS008J	PD	50 to 70 ns	-
		16 M bit	2 M × 8 1 M × 16	S29AS016J	PD	50 to 70 ns	-

Flash Memory (Single 1.8V)

SPANSION™ Products

Flash memory (Single 1.8V)

Organization (W × b)	Part Number	Access Time Max. (ns)	Cycle Time Min. (ns)	V _{CC} Current		Supply Voltage (V)	Operating Temperature Range T _A (°C)	Packages	
				Read (mA)	Standby Mode (μA)			TSOP	FBGA
1 M × 8 512 K × 16	Ⓞ S29AS008J50	50	50	16 (f = 5 MHz)	5	1.65 to 1.95	-40 to +85	48P	48P
	Ⓞ S29AS008J70	70	70						
2 M × 8 1 M × 16	Ⓞ S29AS016J50	50	50	16 (f = 5 MHz)	5	1.65 to 1.95	-40 to +85	48P	48P
	Ⓞ S29AS016J70	70	70						

Ⓞ: Under Developing

Package: P-Plastic

Flash Memory (Single 3V)

SPANSION™ Products

Flash Memory	Supply Voltage	Capacity	Organization	Part Number	Variation	Access Time	Remarks
Flash Memory	Single 3V	4M-bit	512K × 8 256K × 16	S29AL004D	PD	70 to 90 ns	*1
		8M-bit	1M × 8 512K × 16	S29AL008D	PD	70 to 90 ns	*2
				S29AL008J	PD	45 to 55 ns	*2
		16M-bit	2M × 8 1M × 16	S29AL016D	PD	70 to 90 ns	*3
				S29AL016J	PD	45 to 55 ns	*3
		32M-bit	4M × 8 2M × 16	S29AL032D	PD	70 to 90 ns	*4
				S29JL032H	PD SRW	70 to 90 ns	*5
				S29PL032J	PD PM SRW	55 to 70 ns	*6
		64M-bit	8M × 8 4M × 16	S29JL064H	PD SRW	70 to 90 ns	*6
				S29PL064J	PD PM SRW	55 to 70 ns	*6
		128M-bit	8M × 16	S29PL127J	PD PM SRW	55 to 70 ns	*10

Variation
 PD: Automatic sleep mode
 PM: Page mode
 SRW: Simultaneous Read / Write operation (Read-while-program or Read-while-Erase)

MirrorBit is a trademark of Spansion Inc.

- *1 : (16Kbytes × 1sectors) + (8Kbytes × 2sectors) + (32Kbytes × 1sector) + (64Kbytes × 7sectors)
- *2 : (16Kbytes × 1sectors) + (8Kbytes × 2sectors) + (32Kbytes × 1sector) + (64Kbytes × 15sectors)
- *3 : (16Kbytes × 1sectors) + (8Kbytes × 2sectors) + (32Kbytes × 1sector) + (64Kbytes × 31sectors)
- *4 : (16Kbytes × 1sectors) + (8Kbytes × 2sectors) + (32Kbytes × 1sector) + (64Kbytes × 61sectors)
- *5 : (8Kbytes × 8sectors) + (64Kbytes × 63sectors)
- *6 : (8Kbytes × 16sectors) + (64Kbytes × 126sectors)
- *7 : (8Kbytes × 8sectors) + (64Kbytes × 127sectors)
- *8 : (64Kbytes × 128sectors)
- *9 : (8Kbytes × 16sectors) + (64Kbytes × 62sectors)
- *10 : (8Kbytes × 16sectors) + (64Kbytes × 254sectors)

Flash Memory (Single 3V)

SPANSION™ Products

Flash memory (Single 3V)

Organization (W × b)	Part Number	Access Time Max. (ns)	Cycle Time Min. (ns)	V _{CC} Current		Supply Voltage (V)	Operating Temperature Range T _A (°C)	Packages		
				Read (mA)	Standby Mode (μA)			TSOP	FBGA	SOP
512K × 8 256K × 16	S29AL004D70 *	70	70	16 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	48P	44P
	S29AL004D90	90	90							
1M × 8 512K × 16	S29AL008D70 *	70	70	16 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	48P	44P
	S29AL008D90	90	90							
	⊙ S29AL008J45	45	45	16 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	48P	44P
	⊙ S29AL008J55	55	55							
2M × 8 1M × 16	S29AL016D70 *	70	70	16 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	48P	-
	S29AL016D90	90	90							
	⊙ S29AL016J45	45	45	16 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	48P	44P
	⊙ S29AL016J55	55	55							
4M × 8 2M × 16	S29AL032D70 *	70	70	16 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	48P	48P
	S29AL032D90	90	90							
	S29JL032H70	70	70	16 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	-	-
	S29JL032H90	90	90							
	S29PL032J55	55	55	30 (f = 5 MHz)	5	2.7 to 3.6	-45 to +85	-	48P 56P	-
	S29PL032J60	60	60							
	S29PL032J65	65	65							
S29PL032J70	70	70								
8M × 8 4M × 16	S29JL064H70	70	70	16 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	-	-
	S29JL064H90	90	90							
	S29PL064J55	55	55	30 (f = 5 MHz)	5	2.7 to 3.6	-45 to +85	-	48P 56P	-
	S29PL064J60	60	60							
	S29PL064J65	65	65							
	S29PL064J70	70	70							
8M × 16	S29PL127J55	55	55	30 (f = 5 MHz)	5	2.7 to 3.6	-45 to +85	56P	50P	-
	S29PL127J60	60	60							
	S29PL127J65	65	65			2.7 to 3.6				
	S29PL127J70	70	70			1.65 to 1.95				

⊙: Under Developing

* : at C_L = 30pF

Package: P-Plastic

Flash Memory (MirrorBit™) (Single 3 V)

SPANSION™ Products

Flash Memory MirrorBit™	Supply Voltage	Capacity	Organization	Part Number	Variation	Access Time	Remarks
Flash Memory MirrorBit™	Single 3V	32M-bit	4M × 8 2M × 16	S29GL032A	PD PM WB	90 to 110 ns	*1
				S29GL032N	PD PM WB	90 ns	*1
		64M-bit	8M × 8 4M × 16	S29GL064A	PD PM WB	90 to 110 ns	*2
				S29GL064N	PD PM WB	90 ns	*2
		128M-bit	16M × 8 8M × 16	S29GL128N	PD PM WB	90 to 110 ns	*3
				S29GL128P	PD PM WB	90 to 110 ns	*3
		256M-bit	32M × 8 16M × 16	S29GL256N	PD PM WB	90 to 110 ns	*4
				S29GL256P	PD PM WB	90 to 110 ns	*4
		512M-bit	64M × 8 32M × 16	S29GL512N	PD PM WB	100 to 110 ns	*5
				S29GL512P	PD PM WB	100 to 110 ns	*5
		1G-bit	128M × 8 64M × 16	S29GL01GP	PD PM WB	110 to 130 ns	*6

Variation
 PD : Automatic sleep mode
 PM: Page mode
 WB: Write buffer

MirrorBit is a trademark of Spansion Inc.

- *1: Uniform sector model : 32Kword (64Kbytes) × 64sectors
 Boot sector model : 32Kword (64Kbytes) × 63sectors + 4Kword (8Kbytes) × 8sectors
- *2: Uniform sector model : 32Kword (64Kbytes) × 128sectors
 Boot sector model : 32Kword (64Kbytes) × 127sectors + 4Kword (8Kbytes) × 8sectors
- *3: Sector structure - 64Kword (128Kbytes) × 128sectors
- *4: Sector structure - 64Kword (128Kbytes) × 256sectors
- *5: Sector structure - 64Kword (128Kbytes) × 512sectors
- *6: Sector structure - 64Kword (128Kbytes) × 1024sectors

Flash Memory (MirrorBit™) (Single 3 V)

SPANSION™ Products

Flash memory (MirrorBit) (Single 3V)

Organization (W × b)	Part Number	Access Time Max. (ns)	Cycle Time Min. (ns)	V _{CC} Current		Supply Voltage (V)	Operating Temperature Range T _A (°C)	Packages	
				Read (mA)	Standby Mode (μA)			TSOP	FBGA
4M × 8 2M × 16	S29GL032A90	90 (25)	90	25 (f = 5 MHz)	5	3.0 to 3.6	-40 to +85	40P	48P
	S29GL032A10	100 (30)	100					48P	64P
	S29GL032A11	110 (30)	110					56P	
	S29GL032N90	90 (25)	90	40 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	48P
8M × 8 4M × 16	S29GL064A90	90 (25)	90	25 (f = 5 MHz)	5	3.0 to 3.6	-40 to +85	48P	64P
	S29GL064A10	100 (30)	100					56P	
	S29GL064A11	110 (30)	110						
	S29GL064N90	90 (25)	90	40 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	48P	48P
16M × 8 8M × 16	S29GL128N90	90 (25)	90	50 (f = 5 MHz)	5	3.0 to 3.6	-40 to +85	56P	64P
	S29GL128N10	100 (25)	100			2.7 to 3.6			
	S29GL128N11	110 (30)	110						
	S29GL128P90	90 (25)	90	50 (f = 5 MHz)	5	3.0 to 3.6	0 to +70 -40 to +85	56P	64P
	S29GL128P10	100 (25)	100			2.7 to 3.6	-40 to +85		
	S29GL128P11	110 (25)	110						
32M × 8 16M × 16	S29GL256N90	90 (25)	90	50 (f = 5 MHz)	5	3.0 to 3.6	-40 to +85	56P	64P
	S29GL256N10	100 (25)	100			2.7 to 3.6			
	S29GL256N11	110 (30)	110						
	S29GL256P90	90 (25)	90	50 (f = 5 MHz)	5	3.0 to 3.6	0 to +70 -40 to +85	56P	64P
	S29GL256P10	100 (25)	100			2.7 to 3.6	-40 to +85		
	S29GL256P11	110 (25)	110						
64M × 8 32M × 16	S29GL512N10	100 (25)	100	50 (f = 5 MHz)	5	2.7 to 3.6	-40 to +85	56P	64P
	S29GL512N11	110 (30)	110						
	S29GL512P10	100 (25)	100	50 (f = 5 MHz)	5	3.0 to 3.6	0 to +70 -40 to +85	56P	64P
	S29GL512P11	110 (25)	110			2.7 to 3.6	-40 to +85		
	S29GL512P12	120 (25)	120						
128M × 8 64M × 16	S29GL01GP11	110 (25)	110	50 (f = 5 MHz)	5	3.0 to 3.6	0 to +70 -40 to +85	56P	64P
	S29GL01GP12	120 (25)	120			2.7 to 3.6	-40 to +85		
	S29GL01GP13	130 (25)	130						

C_L = 30pF
Package: P-Plastic

Flash Memory (MirrorBit™) (Single 1.8V)

SPANSION™ Products

Flash Memory MirrorBit™	Supply Voltage	Capacity	Organization	Part Number	Variation	Access Time	Remarks
Flash Memory MirrorBit™	Single 1.8V	128 M-bit	8 M × 16	S29WS128N	PD BM SRW HM	9.0 (80 MHz) to 13.5 (54 MHz) ns	*1
				S29WS128P	PD BM SRW HM	7.6 (80 MHz) to 13.5 (54 MHz) ns	*1
		256 M-bit	16 M × 16	S29SW256N	PD BM SRW HM	9.0 (80 MHz) to 13.5 (54 MHz) ns	*2
				S29WS256P	PD BM SRW HM	7.6 (80 MHz) to 13.5 (54 MHz) ns	*2
		512 M-bit	32 M × 16	S29WS512P	PD BM SRW HM	7.6 (80 MHz) to 13.5 (54 MHz) ns	*3

Variation

PD: Automatic sleep mode
 BM: Burst mode
 SRW: Simultaneous Raad/Write operation
 (Read-while-program or Read-while-Erase)
 HM: Hand Shake Mode

*1 : 16 Kword × 8sectors + 64 Kword × 126sectors

*2 : 16 Kword × 8sectors + 64 Kword × 254sectors

*3 : 16 Kword × 8sectors + 64 Kword × 510sectors

MirrorBit is a trademark of Spansion Inc.

Flash Memory (MirrorBit™) (Single 1.8V)

SPANSION™ Products

Flash memory (MirrorBit) (Single 1.8V)

Organization (W × b)	Part Number	Access Time Max. (ns)	Burst Speed (MHz)	V _{CC} Current		Supply Voltage (V)	Operating Temperature Range T _A (°C)	Packages
				Read (mA)	Standby Mode (μA)			FBGA
8 M × 16	S29WS128N0LBxW	80 * ¹ 80/13.5 * ²	54	36 * ³	70	1.70 to 1.95	-25 to +85	84P
	S29WS128N0PBxW	80 * ¹ 80/11.2 * ²	66	42 * ³				
	S29WS128N0SBxW	80 * ¹ 80/9.0 * ²	80	48 * ³				
	S29WS128P0LBxW	80 * ¹ 80/13.5 * ²	54	39 * ³				
	S29WS128P0PBxW	80 * ¹ 80/11.2 * ²	66	43 * ³				
	S29WS128P0SBxW	80 * ¹ 80/9.0 * ²	80	48 * ³				
	S29WS128PABBxW	80 * ¹ 80/7.6 * ²	108	54 * ³				
16 M × 16	S29WS256N0LBxW	80 * ¹ 80/13.5 * ²	54	36 * ³	70	1.70 to 1.95	-25 to +85	84P
	S29WS256N0PBxW	80 * ¹ 80/11.2 * ²	66	42 * ³				
	S29WS256N0SBxW	80 * ¹ 80/9.0 * ²	80	48 * ³				
	S29WS256P0LBxW	80 * ¹ 80/13.5 * ²	54	39 * ³				
	S29WS256P0PBxW	80 * ¹ 80/11.2 * ²	66	43 * ³				
	S29WS256P0SBxW	80 * ¹ 80/9.0 * ²	80	48 * ³				
	S29WS256PABBxW	80 * ¹ 80/7.6 * ²	108	54 * ³				
32 M × 16	S29WS512P0LBxW	80 * ¹ 80/13.5 * ²	54	36 * ³	70	1.70 to 1.95	-25 to +85	84P
	S29WS512P0PBxW	80 * ¹ 80/11.2 * ²	66	43 * ³				
	S29WS512P0SBxW	80 * ¹ 80/9.0 * ²	80	48 * ³				
	S29WS512PABBxW	80 * ¹ 80/7.6 * ²	108	54 * ³				

C_L = 30pF

Package: P-Plastic

*1: Asynchronous access time

*2: Synchronous delay time/burst access time

*3: At burst read Continuous mode (Max.)

Serial Peripheral Interface (MirrorBit™) (Single 3V)

SPANSION™ Products

	Supply Voltage	Capacity	Organization	Part Number	Variation	Access Time	Remarks
Flash Memory MirrorBit™	Single 3V	4 M-bit	4 M × 1	S25FL040A	SI	50 MHz	*1
		8 M-bit	8 M × 1	S25FL008A	SI	50 MHz	*2
		16 M-bit	16 M × 1	S25FL016A	SI	50 MHz	*3
		32 M-bit	32 M × 1	S25FL032A	SI	50 MHz	*4
		64M-bit	64 M × 1	S25FL064A	SI	50 MHz	*5
		128M-bit	128 M × 1	S25FL128P	SI	104 MHz	*6

Variation
SI: Serial interface

*1 : Sector structure - 512 K bits × 8 sectors or 128 K bits × 2 sectors + 32 K bits × 2 sectors + 16 K bits × 2 sectors + 512 K bits × 7 sectors

*2 : Sector structure - 512 K bits × 16 sectors

*3 : Sector structure - 512 K bits × 32 sectors

*4 : Sector structure - 512 K bits × 64 sectors

*5 : Sector structure - 512 K bits × 128 sectors

*6 : Sector structure - 512 K bits × 256 sectors

MirrorBit is a trademark of Spansion Inc.

Serial Peripheral Interface (MirrorBit™) (Single 3 V)

SPANSION™ Products

Flash memory (MirrorBit) (Single 3V)

Organization (W × b)	Part Number	Clock speed (MHz)	V _{CC} Current		Supply Voltage (V)	Operating Temperature Range T _A (°C)	Packages	
			Read (mA)	Standby Mode (μA)			SOIC	SON
4 M × 1	S25FL040A	50	13 (f = 50MHz)	50	2.7 to 3.6	-40 to +85	SOIC8	USON8
8 M × 1	S25FL008A	50	13 (f = 50MHz)	50	2.7 to 3.6	-40 to +85	SOIC8	USON8
16 M × 1	S25FL016A	50	19 (f = 50MHz)	50	2.7 to 3.6	-40 to +85	SOIC8 SOIC16	WSON8 –
32 M × 1	S25FL032A	50	19 (f = 50MHz)	50	2.7 to 3.6	-40 to +85	SOIC16	–
64 M × 1	S25FL064A	50	13 (f = 50MHz)	50	2.7 to 3.6	-40 to +85	SOIC16	–
128 M × 1	S25FL128P	104	22 (f = 104MHz)	200	2.7 to 3.6	-40 to +85	SOIC16	WSON

C_L = 30pF

Package: P-Plastic

Flash Memory (MirrorBit™ ORNAND™) (Single 1.8V)

SPANSION™ Products

	Supply Voltage	Capacity	Organization	Part Number	Variation	Access Time	Remarks
Flash Memory (MirrorBit™ ORNAND™)	Single 1.8V	512 M-bit	32 M × 16 64 M × 8	S30MS512P	ND	8 μs/25 ns	*
				S30MS512R	ND	8 μs/25 ns	*
		1 G-bit	64 M × 16 128 M × 8	S30MS01GP	ND	8 μs/25 ns	*
				S30MS01GR	ND	8 μs/25 ns	*
		2 G-bit	128 M × 16 256 M × 8	S30MS02GR	ND	8 μs/25 ns	*

Variation
ND: NAND interface

* : Block size 128 K + 4 Kbyte

MirrorBit is a trademark of Spansion Inc.
ORNAND is a trademark of Spansion Inc.

Flash Memory (MirrorBit™ ORNAND™) (Single 1.8V)

SPANSION™ Products

Flash memory (MirrorBit ORNAND) (Single 1.8V)

Organization (W × b)	Part Number	Page Access (μs)	Serial Read (ns)	V _{CC} Current		Supply Voltage (V)	Operating Temperature Range T _A (°C)	Packages	
				Read (mA)	Standby Mode (μA)			TSOP	BGA
64 M × 8	S30MS512P25BFW00	8	25	45	60	1.70 to 1.95	-25 to +85	48P	137P
	S30MS512P25TFW00	8	25						-
	○ S30MS512R25TFW00	8	30	50	-				
	○ S30MS01GR25TFW01	8	30		-				
32 M × 16	S30MS512P25BFW01	8	25	45	60	1.70 to 1.95	-25 to +85	48P	137P
	S30MS512P25TFW01	8	25						-
	○ S30MS512R25TFW01	8	30	50	-				
128 M × 8	S30MS01GP25BFW00	8	25	45	60	1.70 to 1.95	-25 to +85	48P	137P
	S30MS01GP25TFW00	8	25						-
	○ S30MS01GR25TFW00	8	30	50	-				
	○ S30MS02GR25TFW01	8	30		-				
64 M × 16	S30MS01GP25BFW01	8	25	45	60	1.70 to 1.95	-25 to +85	48P	137P
	S30MS01GP25TFW01	8	25						-
256 M × 8	○ S30MS02GR25TFW00	8	30	50	60	1.70 to 1.95	-25 to +85	48P	-

○ : New Product

Package: P-Plastic
C_L = 30pF

Memory

Products Scheduled to be out of Production

The productions listed below are scheduled to go out of production.
If you are considering the use in the new applications, select the other series of products

■ FCRAM

Part number	Description
MB82DP02183C-65L	32 Mbit Async. SRAM Type FCRAM
MB82DBS02163C-70L	32 Mbit Async./Sync. SRAM Type FCRAM
MB82DP04183C-65L	64 Mbit Async. SRAM Type
MB82DP04183D-65L	FCRAM
MB82DBS04163C-70L	64 Mbit Async./Sync. SRAM Type
MB82DBS04163D-70L	FCRAM
MB82DBS04314C-70L	128 Mbit Async./Sync. SRAM Type FCRAM

ASIC Product Line-up

ASIC Products

				Page No.	
ASIC Products	Standard cell	CMOS	CS201 series	with on-chip RAM, ROM, ADC/DAC	74
			CS101 series	More than 91,000,000 (on-chip) gates with on-chip RAM, ROM, ADC/DAC	75
			CS91 series	More than 48,000,000 (on-chip) gates with on-chip RAM, ROM, Multipliers, ADC/DAC	76
			CS86 series	More than 40,000,000 (on-chip) gates with on-chip RAM, ROM, FIFO, Delay Line, ADC/DAC	77
			CS81 series	More than 40,000,000 (on-chip) gates, 11 ps/gate with on-chip RAM, ROM, Multipliers, ADC/DAC	78
			CS66 series	More than 1,700,000 (on-chip) gates, 98 ps/gate with on-chip RAM, ROM, Multipliers, ADC/DAC	79
	Macro-embedded type cell arrays	CMOS	CE81 series	Maximum of 34,000,000 (on chip) gates, 12 ps/gate with on-chip RAM, ROM, Multipliers, ADC/DAC	81
			CE77 series	Maximum of 10,000,000 (on chip) gates, 33 ps/gate with on-chip RAM, ROM, FIFO, Delay Line	82
			CE71 series	Maximum of 8,096,000 (on chip) gates, 29 ps/gate with on-chip RAM, ROM, Multipliers, ADC/DAC	84
			CE66 series	Maximum of 1,138,000 (on-chip) gates, 98 ps/gate with on-chip RAM, ROM, Multipliers, ADC/DAC.	86
			CE61 series	Maximum of 2,025,000 (on chip) gates, 85 ps/gate with on-chip RAM/ROM, Multipliers, ADC/DAC	88
	Gate arrays	Sea-of-Gate CMOS	CG61 series	Maximum of 1,568,000 (on chip) gates, 85 ps/gate with on-chip RAM, Analog PLL embedment is possible in some frames	90
			CG47 series	Maximum of 55,000 (on chip) gates, 300 ps/gate with on-chip RAM, FIFO	91
			CG46 series	Maximum of 198,000 (on chip) gates, 300 ps/gate with on-chip RAM, FIFO	92

Standard Cell

■ CS201 Series

Features

Technology : 65 nm Si-gate CMOS
6- to 12-metal layers. Low-k (low permittivity) inter-layer insulation film material is used for all layers.
Consolidation of all 3 kinds of set of cell (energy-saving version to high-velocity version) is possible.

Supply voltage : +1.2 V \pm 0.1 V , +1.0 V \pm 0.1 V

Junction temperature range : -40 °C to +125 °C

Reduced chip sized realized by I/O with pad.

Supports a wide range of cell sets (from low power versions to high speed versions)

IP macros : CPU (ARM11, ARM9, ARM7TDMI), DSP, PCI, IEEE1394, USB, IrDA, PLL, ADC, DAC, and others

Compiled cells (RAM/ROM and others)

It supports energy-saving mode, multi mode SRAM.

It supports energy-saving technology "CoolAdjust"

Supports large capacity memory (1T-SRAM-Q)

High-speed interface macro (up to 10 Gbps)

Special interfaces (LVDS, SSTL and others)

Supports use of industry standard libraries (. LIB)

Uses industry standard tools and supports the optimum tools for the application.

High reliability design estimation in the early stage of physical design realized by physical prototyping tool.

Layout synthesis with optimized timing realized by physical synthesis tools.

Hierarchical design environment for supporting large-scale circuits.

High accuracy design environment considering dynamic drop in power supply voltages, signal noise, delay penalty, and crosstalk.

I/O design environment (power line design, assignment and selection of I/Os, package selection) considering noise.

Supports static timing sign-off

Improved timing settling by introducing Statistical Timing Analysis (SSTA).

Steady product supply and countermeasure for diffusion by introduction of DFM

Supports memory (RAM/ROM) BIST

Supports boundary SCAN

Supports LOGIC BIST

Supports transition delay test

Optimum of package lineup : TEBGA, FBGA, PBGA, FC-BGA

*: "CoolAdjust" is a generic name of Fujitsu Microelectronics's energy-saving technology

Note: Some items are in preparation.

■ CS101 Series

Features

- Optimum gate count : Maximum of 91,000,000 gates
- Technology : 90 nm Si-gate CMOS
 - 6- to 10-metal layers. Low-k (low permittivity) inter-layer insulation film material is used for all layers.
 - 3 types of transistors (low leak, standard, high speed) can be mixed on a chip.
 - The design rules comply with industry standard processes.
- Supply voltage : +1.2 V \pm 0.1 V, +1.0 V \pm 0.1 V
- Junction temperature range : -40 °C to +125 °C (normal)
- Gate delay time : tpd = 12 ps (1.2 V, Inverter, F/O = 1)
- Gate power consumption : Pd = 2.7 nW/MHz/BC (1.2 V, Inverter, F/O = 1)
- Reduced chip sized realized by I/O with pad.
- Supports a wide range of cell sets (from low power versions to high speed versions)
- Compliance with industry standard design rules enables non-Fujitsu commercial macros to be easily incorporated.
- IP macros : CPU (ARM9, ARM7TDMI) , DSP, PCI, IEEE1394, USB, IrDA, PLL, ADC, DAC, and others
- Compiled cells (RAM/ROM and others)
- High-speed interface macro (up to 10 Gbps)
- Special interfaces (LVDS, SSTL_2 and others)
- Supports use of industry standard libraries (. LIB)
- Uses industry standard tools and supports the optimum tools for the application.
- High reliability design estimation in the early stage of physical design realized by physical prototyping tool.
- Layout synthesis with optimized timing realized by physical synthesis tools.
- Hierarchical design environment for supporting large-scale circuits.
- High accuracy design environment considering drop in power supply voltages, signal noise, delay penalty, and crosstalk.
- I/O design environment (power line design, assignment and selection of I/Os, package selection) considering noise.
- Supports static timing sign-off
- Supports memory (RAM/ROM) BIST
- Supports boundary SCAN
- Supports LOGIC BIST
- Supports transition delay test

Optimum of package lineup : TEBGA, FBGA, PBGA, FC-BGA

Note: Some items are in preparation.

Standard Cell

■ CS91 Series

Features

- Optimum gate count : Maximum of 48,000,000 gates
- Technology : 0.11 μm Si-gate CMOS, 5- to 8-layer wiring (Copper is used as wire material) ,
Low-k Inter-layer material
(Inter-layer material that has low permittivity)
- Supports 8 types of cell sets that differ in speed, integration, and power consumption.
These cell sets can be mixed on a chip.
- Supply voltage : +1.2 V \pm 0.1 V (normal)
- Junction temperature range : -40 to +125 $^{\circ}\text{C}$
- Gate delay time : $t_{pd} = 16$ ps (1.2 V, Inverter, F/O = 1)
- Gate power consumption : $P_d = 6.6$ nW/MHz (1.2 V, Inverter, F/O = 1)
- High-speed interface macro (up to 10 Gbps)
- Special interfaces: P-CML, LVDS, PCI, USB, SSTL, HSTL, T-LVTTL, and others
- Buffer cells for crystal oscillation circuits.
- IP macros : CPU (ARM9, ARM7TDMI) , DSP, PCI, IEEE1394, USB, IrDA, PLL, ADC, DAC, and others
- Compiled cells (RAM/ROM/multiplier and others)
- Uses industry standard tools and supports the optimum tools for the application.
- Short-term development using a physical prototyping tool.
- Hierarchical design environment for supporting large-scale circuits.
- Supports Signal Integrity, EMI noise reduction
- Supports High resolution RC extraction base delay calculation environment
- Supports optimization environment of power supply wire
- Supports static timing sign-off
- Supports memory (RAM/ROM) BIST
- Supports boundary SCAN
- Supports LOGIC BIST
- Supports transition delay test
- A variety of package options : FC-BGA (Max. 2116 pin), EBGA, HQFP, FBGA and others

Note: Some items are in preparation.

CS86 Series

Features

Optimum gate count : Maximum of 40,000,000 gates
 Technology : 0.18 μm Si-gate CMOS, 4- to 6-layer wiring
 Supports three types of internal cell sets (ultra high-speed, standard, low-leak)
 Capable of integrating a mixture of standard transistor cell and ultra high-speed process/cell, and mixture of standard transistor cell and low leak process/cell on a single chip

Supply voltage : +1.8 V \pm 0.15V (normal) to +1.1V \pm 0.1V
 Gate delay time : tpd = 88 ps (standard : 1.8 V, 2NAND, F/O = 2, standard load)
 tpd = 70 ps (ultra high-speed : 1.8 V, 2NAND, F/O = 2, standard load)
 tpd = 136 ps (low-leak : 1.8 V, 2NAND, F/O = 2, standard load)
 Leakage Current : 0.023 nW (standard : 1.8 V, 2NAND, F/O = 0, no load)
 3.922 nW (ultra high-speed : 1.8 V, 2NAND, F/O = 0, no load)
 0.0067 nW (low-leak : 1.8 V, 2NAND, F/O = 0, no load)
 Gate power consumption : 40.1 nW/MHz (standard : 1.8 V, 2NAND, F/O = 1, 4Grid)
 42.7 nW/MHz (ultra high-speed : 1.8 V, 2NAND, F/O = 1, 4Grid)
 38.3 nW/MHz (low-leak : 1.8 V, 2NAND, F/O = 1, 4Grid)

Junction temperature range : -40 to +125 $^{\circ}\text{C}$

Output buffer cells with noise reduction circuits

Inputs with on-chip input pull-up/pull-down resistors and bidirectional buffer cells.

Buffer cells for crystal oscillation circuits.

Special interfaces : SSTL2, PCI, P-CML, T-LVTTL, USB2.0, IEEE1394, and others

IP macros : CPU (FR-V, ARM9, and others), DSP, PCI, IEEE1394, USB2.0, IrDA, PLL, ADC, DAC, and others

Compiled cells (RAM/ROM/FIFO/Delay line, and others)

Configurable internal bus circuits

Advanced for hardware/software co-design environment

Short-term development using a physical synthesis tool

Low-power dissipation using a low power synthesis tool

Short-term development using a timing driven layout tool

Hierarchical design environment for supporting large-scale circuits

Supports signal Integrity

Supports memory (RAM, ROM) SCAN

Supports memory (RAM) BIST

Supports boundary SCAN

Supports path delay test

Supports transition delay test

A variety of package options (QFP, TQFP, LQFP, HQFP, PBGA, FBGA, FLGA, EBGA)

Note: Some items are in preparation.

Packages

The table below lists the available package types.

Type	Pin Count	Material
QFP	176, 208, 240	Plastics
TQFP	100, 120	Plastics
LQFP	144, 176, 208, 256	Plastics
HQFP	208, 240, 256, 304	Plastics
PBGA	256, 352, 420	Plastics
FBGA	112, 144, 168, 176, 192, 224, 272, 288, 240, 304, 368	Plastics
FLGA	144, 176, 208, 224, 288	Plastics
EBGA	660	Plastics

Note: This list contains packages under planning. Contact Fujitsu Microelectronics for the availability.

Standard Cell

■ CS81 Series

Features

Optimum gate count : Maximum of 40,000,000 gates
Technology : 0.18 μm Si-gate CMOS, 3- to 6-layer wiring
Capable of integrating a mixture of high-speed processes and cells on a single chip
Supply voltage : +1.8 V \pm 0.15V (normal) to +1.1V \pm 0.1V
Gate delay time : tpd = 11 ps (1.8 V, Inverter, F/O = 1)
Gate power consumption : 5nW/MHz/BC (1.1V, 2NAND, F/O = 1)
Junction temperature range : -40 to +125 $^{\circ}\text{C}$
High-speed interface macro (up to 3.125 Gbps)
Output buffer cells with noise reduction circuits
Inputs with on-chip input pull-up/pull-down resistors (33 k Ω typical) and bidirectional buffer cells.
Buffer cells for crystal oscillation circuits.
Special interfaces: P-CML, LVDS, PCI, AGP, USB, SDRAM-I/F, SSTL, and others
IP macros: CPU, DSP, PCI, IEEE1394, USB, IrDA, PLL, ADC, DAC, and others
Compiled cells (RAM/ROM/multiplier, and others)
Configurable internal bus circuits
Advanced for hardware/software co-design environment
Short-term development using a timing driven layout tool
Supports static timing sign-off
Dramatically reducing the time for generating test vectors for timing verification and the simulation time
Hierarchical design environment for supporting large-scale circuits
Simulation (before layout) considering the input through rate and high resolution RC extraction base delay calculation (after layout), supporting development with minimized timing trouble after trial manufacture.
Supports signal Integrity, EMI noise reduction
Supports memory (RAM, ROM) SCAN
Supports memory (RAM) BIST
Supports boundary SCAN
Supports At-Speed test on internal circuits
Supports path delay test
Supports transition delay test
A variety of package options (TQFP, HQFP, EBGA, FBGA, TAB-BGA, FC-BGA, LQFP)

Note: Some items are in preparation.

Packages

The table below lists the available package types.

Type	Pin Count	Material
TAB-BGA	304, 352, 480 560, 660, 720	Plastics
EBGA	576, 660, 672	Plastics
HQFP	208, 240, 256, 304	Plastics
TQFP	100, 120	Plastics
LQFP	144, 176, 208	Plastics
FBGA	288	Plastics
FC-BGA	1089, 1225, 1369, 1681, 1849, 2116	Plastics, Ceramic

Note: This list contains packages under planning. Contact Fujitsu Microelectronics for the availability.

Standard Cell

Number of gates used in each package

The table below lists the available package types and the reference number of gates used.

CS66 (P-frame)

Package and pin count		0	2000K	4000K	6000K	8000K	10000K	12000K	14000K	16000K
TQFP	100	_____ 1579K								
LQFP	100	_____ 1579K								
	144	_____ 1579K								
	176	_____ 1579K								
	208	_____ 1305K								
QFP	120	_____ 1579K								
	144	_____ 1579K								
	160	_____ 1579K								
	176	_____ 1579K								
	208	_____ 1579K								
	240	_____ 1579K								
HQFP	208	_____ 1579K								
	240	_____ 1579K								
	256	_____ 1579K								
	304	_____ 1579K								
PBGA	256	_____ 1579K								
	352	_____ 1579K								
FBGA	112	_____ 639K								
	144	_____ 639K								
	168	_____ 835K								
	176	_____ 1305K								
	192	_____ 1579K								
	224	_____ 1579K								
	288	_____ 1579K								

Note: This list contains packages under planning.

CS66 (S-frame)

Package and pin count		0	100K	200K	300K	400K	500K	600K	700K	800K	900K
TQFP	100	_____ 158K									
LQFP	100	_____ 158K									
	144	_____ 158K									
	208	_____ 433K									
QFP	120	_____ 158K									
	144	_____ 158K									
	160	_____ 228K									
	176	_____ 228K									
	208	_____ 358K									
HQFP	208	_____ 545K									
	240	_____ 358K									
	256	_____ 545K									
PBGA	256	_____ 545K									
	352	_____ 807K									
FBGA	112	_____ 192K									
	144	_____ 228K									
	168	_____ 433K									
	176	_____ 228K									
	192	_____ 289K									
	224	_____ 433K									
	288	_____ 807K									

Note: This list contains packages under planning.

Macro-Embedded Type Cell Arrays

■ CE81 Series

Features

- High Integration : Maximum of 34,000,000 BCs
- Technology : 0.18 μ m Si-gate CMOS, 4- to 5-layer wiring
- Supply voltage : +1.8 V \pm 0.15 V (normal) to +1.1 V \pm 0.1 V
- Gate delay time : tpd = 12 ps (1.8V, Inverter, F/O = 1)
- Gate power consumption : 8nW/MHz/BC (1.1V, 2NAND, F/O = 1)
- Junction temperature range : -40 to +125 $^{\circ}$ C
- Output buffer cells with noise reduction circuits
- Inputs with on-chip input pull-up/pull-down resistors (33 k Ω typical) and bidirectional buffer cells.
- Buffer cells for crystal oscillation circuits.
- Special interfaces: P-CML, LVDS, PCI, AGP, USB, SDRAM-I/F, SSTL, and others
- IP macros: CPU, DSP, PCI, IEEE1394, USB, IrDA, PLL, ADC, DAC, and others
- Compiled cells (RAM/ROM/multipliers, and others)
- Configurable internal bus circuits
- Advanced for hardware/software co-design environment
- Short-term development using a timing driven layout tool
- Supports static timing sign-off
- Dramatically reducing the time for generating test vectors for timing verification and the simulation time.
- Hierarchical design environment for supporting large-scale circuits
- Supports optimization environment of power supply wire
- Simulation (before layout) considering of the input through rate and high resolution RC extraction base delay calculation (after layout), supporting development with minimized timing trouble after trial manufacture.
- Supports Signal Integrity
- Supports memory (RAM, ROM) SCAN
- Supports memory (RAM) BIST
- Supports boundary SCAN
- Supports At-Speed test on internal circuits
- Supports path delay test
- Supports transition delay test
- A variety of package options (TQFP, HQFP, EBGA, FBGA, TAB-BGA, LQFP)
- Note: Some items are in preparation.

ASIC

Number of gates used in package

The table below lists the available package types and the reference number of gates used.

Package and pin count		0	2000K	4000K	6000K	8000K	10000K	12000K	14000K	16000K	
TAB-BGA	304	— 891K									
	352	— 1254K									
	480	— 1905K									
	560	— 2689K									
	660	— 3609K									
	720	— 9129K									
EBGA	576	— 5982K									
	660	— 9805K									
	672	— 7952K									
HQFP	208	— 1098K									
	240	— 2085K									
	256	— 3764K									
	304	— 15158K									
	304	— 4712K									
TQFP	100	— 514K									
	120	— 514K									
LQFP	144	— 722K									
	176	— 722K									
	208	— 1098K									
FBGA	288	— 4712K									

Note: This list contains packages under planning.

Macro-Embedded Type Cell Arrays

■ CE77 Series

Features

- High integration : Maximum of 10,000,000 BCs
- Technology : 0.25 μm Si-gate CMOS, 3- to 4-layer wiring
- Supply voltage : +2.5 V ± 0.2 V (normal) to +1.5 V ± 0.1 V
- Junction temperature range : -40 to +125°C
- Gate delay time : $t_{pd} = 33$ ps (2.5 V, Inverter, F/O = 1, No load)
- Gate power consumption : 0.02 μW/MHz (1.5 V, Inverter, F/O = 1, No load)
- High-load driving capability : $I_{OL} = 2\text{mA}/4\text{mA}/8\text{mA}/12\text{mA}$ mixable.
- Output buffer cells with noise reduction circuits
- Inputs with on-chip input pull-up/pull-down resistors (25 kΩ typical) and bidirectional buffer cells.
- Buffer cells for crystal oscillation circuits.
- Special interfaces (P-CML, LVDS, T-LVTTL, SSTL, PCI, USB, GTL+, and others)
- IP macros (CPU, PCI, USB, IrDA, PLL, DAC, ADC, and others)
- Compiled cells (RAM/ROM/FIFO/Delay Line, and others)
- Configurable internal bus circuits
- Advanced for hardware/software co-design environment
- Short-term development using a timing driven layout tool
- Hierarchical design environment for supporting large-scale circuits
- Supports static timing sign-off
- Dramatically reducing the time for generating test vectors for timing verification and the simulation time.
- Simulation (before layout) considering the input through rate and detailed RC delay calculation (after layout), supporting development with minimized timing trouble after trial manufacture.
- Supports memory (RAM, ROM) SCAN
- Supports memory (RAM) BIST
- Supports boundary SCAN
- Supports path delay test
- A variety of package options (SQFP, LQFP, HQFP, FBGA, PBGA)

Note: Some items are in preparation.

Number of gates used in each package

The table below lists the available package types and the reference number of gates used.

CE77 (V-Frame)

Package and pin count		0 1000k 2000k 3000k 4000k 5000k 6000k 7000k 8000k 9000k	Material
SQFP	176	— 274k	P
	208	— 803k	P
	240	— 965k	P
HQFP	208	— 1776k	P
	240	— 2276k	P
	256	— 1776k	P
	304	— 7128k	P
PBGA	256	— 618k	P

P: Plastic

Note: This list contains packages under planning.

Macro-Embedded Type Cell Arrays

CE77 (T-Frame)

Package and pin count		0 500K 1000K 1500K 2000K 2500K 3000K 3500K 4000K 4500K 5000K	Material
LQFP	144	976 K	P
	176	744 K	P
	208	1375 K	P
	256	1841 K	P
HQFP	208	1375 K	P
	240	1609 K	P
	256	2109 K	P
	304	4538 K	P
FBGA	144	461 K	P
	176	646 K	P
	224	1375 K	P
	288	2109 K	P
PBGA	256	1841 K	P
	352	2678 K	P
	420	3789 K	P

P: Plastic

Note: This list contains packages under planning.

ASIC

Macro-Embedded Type Cell Arrays

■ CE71 Series

Features

- High integration : Maximum of 8,000,000 BCs
- Technology : 0.25 μm Si-gate CMOS, 3- to 4-layer metal wiring
- Supply voltage : +2.5 V \pm 0.2 V (normal) to +1.5 V \pm 0.1 V
(5 V TTL interface is available if 5 V tolerant I/O is adopted. Some frames are under development.)
- Gate delay time : $t_{pd} = 29$ ps (2.5 V, Inverter, F/O = 1, No load)
- Gate power consumption : 0.060 $\mu\text{W}/\text{MHz}$ (F/O = 1, No load)
- Junction temperature range : -40 to +125°C
- High-load driving capability : $I_{OL} = 2$ mA/4 mA/8 mA/12 mA mixable.
- Output buffer cells with noise reduction circuits
- Inputs with on-chip input pull-up/pull-down resistors (25 k Ω typical) and bidirectional buffer cells.
- Buffer cells for crystal oscillation circuits.
- Special interfaces (P-CML, LVDS, SDRAM-I/F, SSTL, and others)
- IP macros (SPARClike, FR40, F²MC16LX, PCI, IEEE1394, USB, IrDA, PLL, ADC/DAC, and others)
- Compiled cells (RAM/ROM/multipliers, and others)
- Configurable internal bus circuits
- Advanced for hardware/software co-design environment
- Linking floor plan tools and logic synthesis tools allows automatic optimization of the circuits using the floor plan information. The Clock Driven Design Method (CDDM) clock tree synthesis tools using the floor plan information are also available. Using the floor plan information in the pre-layout stage would eliminate the problems of setup after layout or timing problems for hold, significantly reducing the time to market.
- Supports the static timing sign off using the Synopsys CAD tool Prime Time. This contributes to the considerable reduction of time required for test vector creation for timing verification and the simulation time.
- Simulation (before layout) considering the input through rate and detailed RC delay calculation (after layout), supporting development with minimized timing trouble after trial manufacture.
- Supports memory (RAM, ROM) SCAN
- Supports memory (RAM) BIST
- Supports boundary SCAN
- A variety of package options (SQFP, LQFP, HQFP, PBGA, EBGA, TAB-BGA, FBGA)

Note: Some items are in preparation.

Number of gates used in each package

The table below lists the available package types and the reference number of gates used.

CE71 (J-Frame)

Package and pin count		0	1000 K	2000 K	3000 K	4000 K	5000 K	Material
SQFP	176	■ 203 K						P
	208	■ 592 K						P
	240	■ 714 K						P
HQFP	208	■ 1313 K						P
	240	■ 1681 K						P
	256	■ 1313 K						P
	304	■ 5345 K						P
PBGA	256	■ 457 K						P
EBGA	352	■ 991 K						P
	420	■ 1313 K						P
	576	■ 1986 K						P
	660	■ 5345 K						P
	672	■ 2673 K						P

P: Plastic

Note: This list contains packages under planning.

Macro-Embedded Type Cell Arrays

CE71 (L-Frame)

Package and pin count		0 1000 K 2000 K 3000 K 4000 K 5000 K	Material
TAB-BGA	304	310 K	P
	352	672 K	P
	480	672 K	P
	560	2279 K	P
	660	1284 K	P
	720	3278 K	P

Note: This list contains packages under planning.
P: Plastic

CE71 (T-Frame)

Package and pin count		0 1000 K 2000 K 3000 K 4000 K 5000 K	Material
LQFP	144	341 K	P
	176	477 K	P
	208	1014 K	P
	256	1358 K	P
HQFP	208	1014 K	P
	240	1188 K	P
	256	1559 K	P
	304	3349 K	P
FBGA	144	341 K	P
	176	477 K	P
	224	1014 K	P
	288	1559 K	P
PBGA	256	1358 K	P
	352	1976 K	P
	420	2794 K	P

Note: This list contains packages under planning.
P: Plastic

Macro-Embedded Type Cell Arrays

■ CE66 Series

Features

- High integration : Maximum of 1,138,000 BCs
- Technology : 0.35 μm Si-gate, 3- to 4-layer metal wiring
- Supply voltage : +3.3 V \pm 0.3 V (normal) to +2.0 V \pm 0.1 V
 - +5.0 V \pm 10% (only for external interface; when internal requirements is 3.3 V)
 - +3.3 V \pm 10% (only for external interface; when internal requirements is 3.3 to 2.0 V)
- Gate delay time : $t_{pd} = 98$ ps (high-speed type, F/O = 2, standard load)
- Gate power consumption : 0.29 $\mu\text{W}/\text{MHz}$ (F/O = 2, standard load)
- Junction temperature range : - 40 to 125°C
- High-load driving capability : $I_{OL} = 2$ mA/4mA/8mA/12mA/24mA mixable.
- Output buffer cells with noise reduction circuits
- On-chip input pull-up/pull-down resistors (50 k Ω typical)
- Buffer cells dedicated to crystal oscillator
- Configurable internal bus circuits
- Highly integrated RAM/ROM/multipliers mountable; arbitrary words/bits configurable.
- Clock skew layout design method (CDDM) based on the floor plan information minimizes post-layout circuit modification, reducing turnaround time for development.
- Simulation (before layout) considering the input through rate and detailed RC delay calculation (after layout), supporting development with minimized timing trouble after trial manufacture.
- Special interfaces (T-LVTTL and SDRAM-I/F, and others)
- Analog PLL
- Analog circuits (ADC, DAC, OPAMP and others)
- Macros for system ASICs (CPU core, CPU peripheral, operational macros, and others)
- Supports DFF scan test with MUX
- Supports memory (RAM/ROM) SCAN
- Supports memory (RAM) BIST
- Supports boundary SCAN

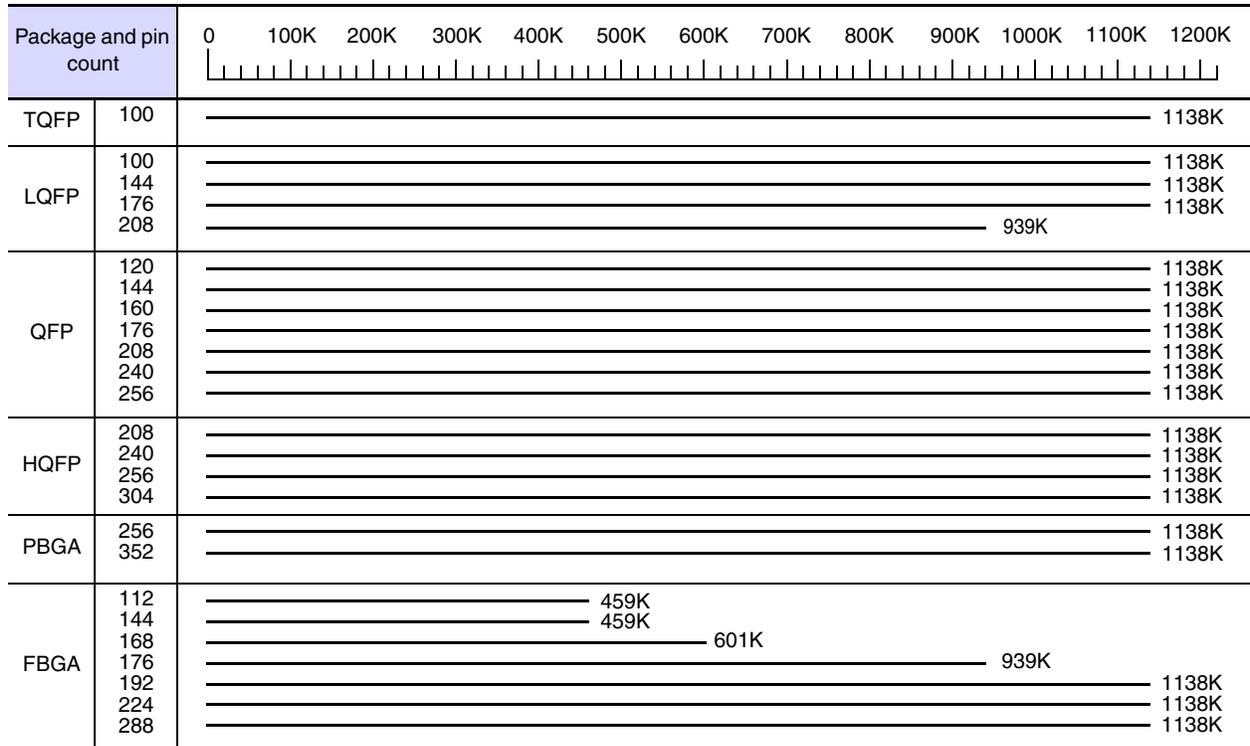
Note: Some items are in preparation.

Macro-Embedded Type Cell Arrays

Number of gates used in each package

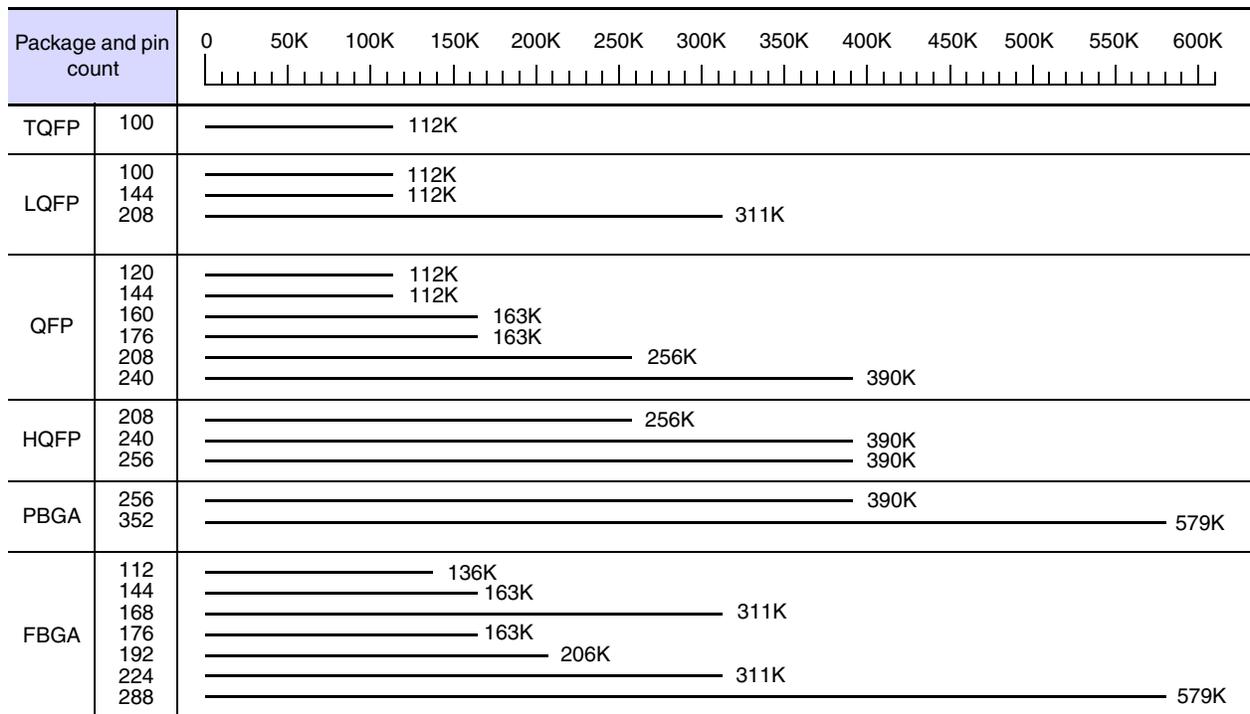
The table below lists the available package types and the reference number of gates used.

CE66 (P-frame)



Note: This list contains packages under planning.

CE66 (S-frame)



Note: This list contains packages under planning.

Macro-Embedded Type Cell Arrays

■ CE61 Series

Features

- High Integration : Maximum of 2,000,000 BCs
- Technology : 0.35 μm Si-gate 3-layer metal wiring/4-layer metal wiring
(There are restrictions applicable frames)
- Basic circuit (basic cell) : 2-input NAND/2-input NOR gates
- Supply voltage : +3.3 V \pm 0.3 V (normal) to +2.0 V \pm 0.1 V
High voltage tolerant transistor for I/O; interface provided for 5 V devices
(Also requiring a 5 V power supply for interface with 5 V devices)
- Gate delay time : High-speed type, $t_{pd} = 85$ ps (2-input NAND, F/O = 2, standard load)
- Junction temperature range : 0 to +100°C
- High-load driving capability : $I_{OL} = 2$ mA/4 mA/8 mA/12 mA/24 mA mixable.
- Power consumption : Reduced to 50% to 20% (over the CE51 Series)
- Output buffer cells with noise reduction circuits
- On-chip input pull-up/pull-down resistors (Typ. 50k Ω)
- Buffer cells for crystal oscillation circuits.
- Configurable internal bus circuits
- Super high-integration RAM and ROM available. Compilable bit/word configuration
- Clock skew reduction layout design technique (CDDM) employed to minimize circuit modification after layout, reducing TAT
- Simulation (before layout) considering the input through rate and detailed RC delay calculation (after layout), supports development with minimized timing trouble after trial manufacture.
- Supports high speed interfaces [P-CML (200 MHz transmission), LVDS (250 MHz transmission), and SDRAM I/F, PCI, 5 V tolerant, USB, IEEE 1284]
- PLL circuits
- Analog circuits (ADC, DAC)
- Macros for system ASICs (CPU core and CPU peripheral and operational macros, and others)
- Supports tests (for function/DC) using DFF scan with MUX
- Supports the test for RAM BIST, RAM SCAN and ROM SCAN
- Supports the Boundary SCAN
- Now under preparation on for a narrow-pitch pad technology and high-pin count BGA packages to be added to the current lineup
- Variety of package options to optimize any gate size

Note: Some items are in preparation.

Macro-Embedded Type Cell Arrays

Number of gates used in each package)

The table below lists the available package types and the reference number of gates used."

CE61 (F10 to F80)

Package and pin count		0 100K 200K 300K 400K 500K 600K 700K 800K 900K 1000K1100K1200K1300K	Material	
QFP	64	86K	P	
	80	86K	P	
	100	86K	P	
	120	86K	P	
	144	593K	P	
	160	1317K	P	
	160	981K	C	
	176	593K	P	
	176	1317K	C	
	208	1317K	P	
	208	1317K	C	
LQFP	64	86K	P	
	80	86K	P	
	100	86K	P	
	HQFP	208	1317K	P
		240	981K	P
		256	1317K	P
304		981K	P	
BGA	256	593K	P	
	352	981K	P	
	420	981K	P	
PGA	256	1317K	C	
	299	1317K	C	
	361	981K	C	
	401	1317K	C	

P : Plastic C : Ceramic

Note: This list contains packages under planning.

CE61 (E7 to E71)

Package and pin count		0 100K 200K 300K 400K 500K 600K 700K 800K 900K 1000K 1100K	Material
QFP	120	509K	P
	144	509K	P
	160	747K	P
	176	509K	P
	208	747K	P
	240	747K	P
	256	747K	P
LQFP	64	78K	P
	80	128K	P
	100	128K	P
HQFP	208	1029K	P
	240	1029K	P
	256	1029K	P
	304	1029K	P
BGA	256	391K	P
	352	391K	P
	420	509K	P
	576	747K	P
	672	1029K	P

P : Plastic

Note: This list contains packages under planning.

Sea-of-Gate Type CMOS Gate Arrays

■ CG61 Series (Analog PLL embedment is possible in some frames)

Features

- High Integration : 1,560,000 BCs
- Technology : 0.35 μm Si-gate CMOS, 3-layer metal wiring
- Basic circuit (basic cell) : 2-input NAND/2-input NOR gates
- Supply voltage : +3.3 V \pm 0.3 V (normal) to +2.0 V \pm 0.1 V
(5 V TTL interface is possible when 5 V tolerant I/Os are used.)
- Gate delay time : $t_{pd} = 85$ ps (3.3 V, 2-input NAND, F/O = 2, standard load)
- Gate power dissipation : 0.24 $\mu\text{W}/\text{MHz}$ (2.0 V, 2-input NAND, F/O = 2, standard load)
- Junction temperature range : 0 to +100 $^{\circ}\text{C}$
- High-load driving capability : $I_{OL} = 2$ mA/4 mA/8 mA/12 mA/24 mA mixable
- Output buffer cells with noise reduction circuits
- On-chip input pull-up/pull-down resistors (Typ. 50 k Ω <at 3.3 V>)
- Buffer cells for crystal oscillation circuits
- Configurable internal bus circuits
- Compiled RAM can be embedded. Compatible bit/word configuration
- An analog PLL can be embedded in CG61P only.
- Clock skew reduction layout design technique (CDDM) employed to minimize circuit modification after layout, reducing TAT
- Simulation (before layout) considering the input through rate and detailed RC delay calculation (after layout), supports development with minimized timing trouble after trial manufacture.
- Supports high speed interfaces (T-LVTTL, P-CML, LVDS, SDRAM I/F)
- Supports tests using DFF scan with MUX
- Supports the test for RAM BIST and RAM SCAN

Number of gates used in each package

The table below lists the available package types and the reference number of gates used.

CG 61 (The frame which cannot use Analog PLL)

Package and pin count		0	100K	200K	300K	400K	500K	600K	700K	800K	900K	Material
LQFP	120	_____ 222K										P
	144	_____ 222K										P
QFP	240	_____ 222K										P
	256	_____ 395K										P
HQFP	208	_____ 802K										P
	240	_____ 580K										P
	256	_____ 580K										P
	304	_____ 802K										P

P: plastic

Note: This list contains packages under planning.

CG 61P (The frame which can use Analog PLL)

Package and pin count		0	20K	40K	60K	80K	100K	120K	140K	160K	180K	200K	Material
LQFP	48	_____ 16K											P
	64	_____ 88K											P
	80	_____ 188K											P
	100	_____ 188K											P
	120	_____ 188K											P
	144	_____ 188K											P
	176	_____ 188K											P
QFP	240	_____ 188K											P
	256	_____ 188K											P
BCC	48	_____ 88K											P
	64	_____ 88K											P

P: plastic

Note: This list contains packages under planning.

Sea-of-Gate Type CMOS Gate Arrays

■ CG47 Series

Features

High integration : Maximum 55,000 BCs (on chip)
 Technology : 0.65 μm Si-gate CMOS, 2-layer metal wiring
 Gate delay time : 300ps (power type 2-input NAND, standard load)
 Supply voltage : [Single power supply] +5 V ± 5%(normal), +3.3 V ± 0.3 V (normal)
 [Dual power supply] Internal domain: +3.3 V ± 0.3 V, +5 V ± 5% (cannot be mixed)
 I/O: +3.3 V ± 0.3 V, +5 V ± 5% (can be mixed)

Interface enabled between dual power sources

Low power consumption enabled by operating internal supply voltage at 3.3V.

Delay time estimation by detailed time equations

Detailed time equations can be used for the estimation of delay time closer to that of actual devices.

Buffer cells for crystal oscillations circuits

Supports separate low frequency (32 kHz), and high frequency (1 to 40MHz) buffers, and oscillator stop function.

Supports output open drain cell and input fail safe cells

Compiled cells include single port RAM, dual port RAM, and FIFO memory.

Note: The type of the RAM that can be used is specified depending on the internal power supply when the RAM is a single-port RAM.

HISCAN (scan circuit automatic generation function)

HISCAN is supported with single power supply, but dual power supply specifications and HISCAN are mutually exclusive.

Simple interface

CAD-to-CAD interface uses special language for logic data (FLDL) and test data (FTDL).

Integrated development tools

Number of gates used in each package

The table below lists the available package types and the reference number of gates used.

Package and pin count		0	5K	10K	15K	20K	25K	30K	35K	40K	45K	50K
SSOP	30	———— 2K										
LQFP	48	———— 11K										
	64	———— 21K										
	80	———— 33K										
	100	———— 33K										
	120	———— 33K										
	144	———— 33K										
	176	———— 33K										
208	———— 33K											
QFP	64	———— 21K										
	80	———— 21K										
	100	———— 21K										
	240	———— 33K										
BCC	48	———— 21K										
	64	———— 31K										
	80	———— 31K										

Note: This list contains packages under planning.

Sea-of-Gate Type CMOS Gate Arrays

■ CG46 Series

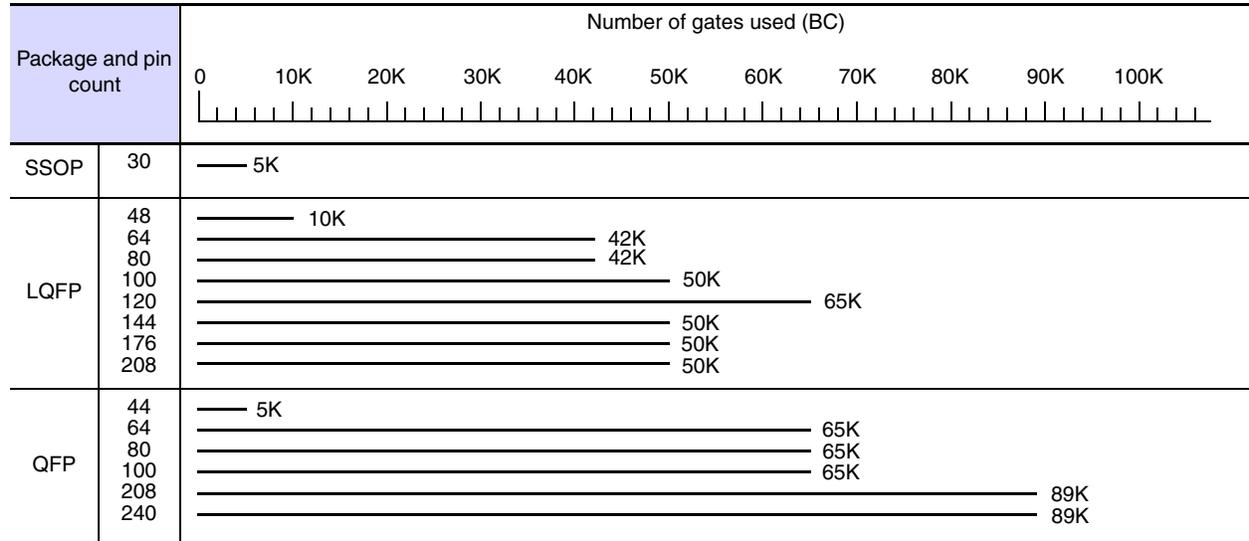
Features

- High integration : Maximum 198,084 BCs (on chip)
- Technology : 0.65 μm Si-gate CMOS, 2-layer metal wiring
- Basic circuit (basic cell) : 2-input NAND/2-input NOR gates
- Input level : TTL/CMOS level mixable
- Supply voltage : +5 V \pm 5% (normal)
+3.3 V \pm 0.3 V (optional)
- Gate delay time : Standard gate tpd = 360 ps (2-input NAND, standard load)
Power gate tpd = 300 ps (2-input NAND, standard load)
- Operating temperature : 0 to +70°C
- High-load driving capability : $I_{OL} = 3.2 \text{ mA}/8 \text{ mA}/12 \text{ mA}/24 \text{ mA}$ mixable
- Output buffer cells with noise reduction circuits
- On-chip input pull-up/pull-down resistors (Typ. 50 k Ω)
- Buffer cells for crystal oscillations circuits
- Configurable internal bus circuits
- RAM and FIFO memory allowing arbitrary bit/word configuration
- Clock skew reduction layout design technique (CDDM) employed to minimize circuit modification after layout, reducing the period of time for development
- Detailed RC delay calculation minimized timing trouble after trial manufacture.
- Supports ATG (Automatic Test Generation) based on scan design
- Supports HISCAN (automatic scan generation)
- Simplified interface: CAD-to-CAD interface uses special language for logic data (FLDL) and test data (FTDL) .
- Integrated development tools

Sea-of-Gate Type CMOS Gate Arrays

Number of gates used in each package

The table below lists the available package types and the reference number of gates used.

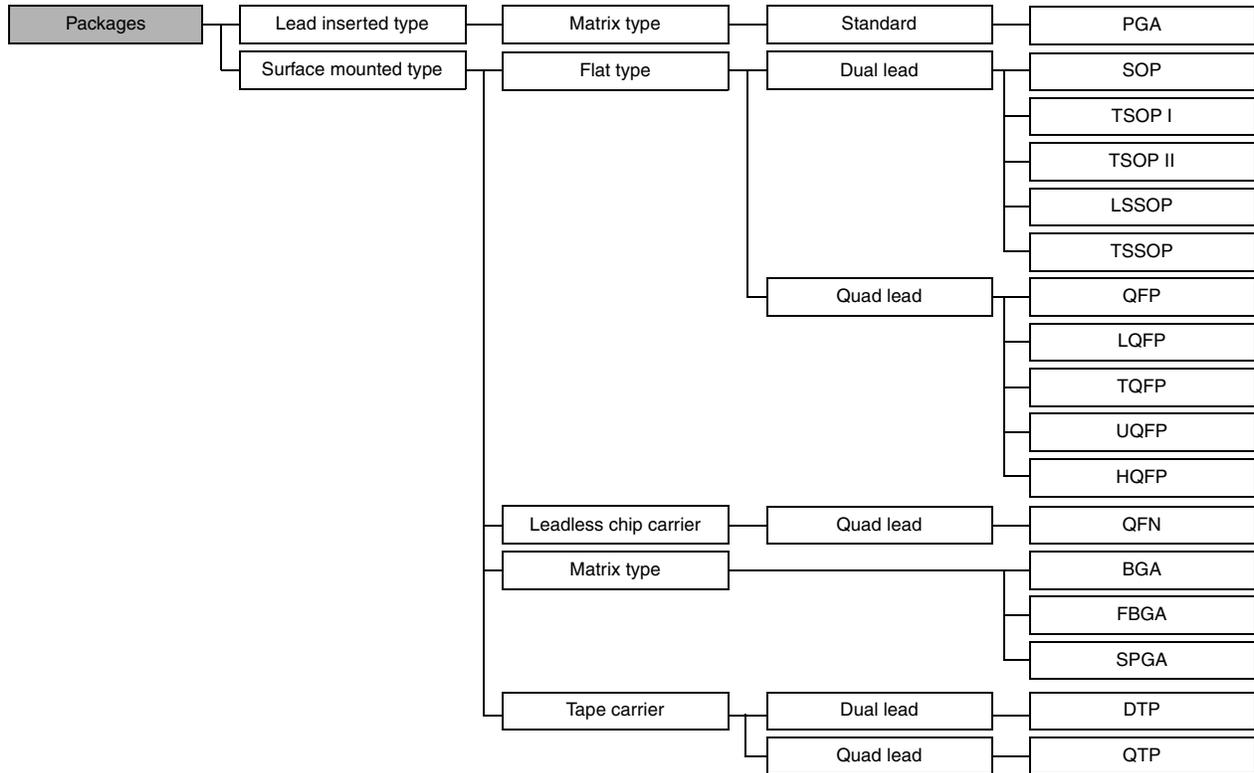


Note: This list contains packages under planning.

Package Line-up

■ Package Line-up

The packages are classified as follows, according to form, material, and the mounting methods for which they are suited.



Package Line-up

Name of package	Description	Lead pitch (mm)
PGA	Pin Grid Array Package	1.27/2.54
SOP	Small Outline Package (straight lead) Small Outline L-Leaded Package	1.27
SOL ^{*2}	Small Outline L-Leaded Package (JEDEC ^{*1})	1.27
SSOP	Shrink Small Outline L-Leaded Package	0.65/0.80/1.00
TSOP (I)	Thin Small Outline L-Leaded Package (I)	0.50/0.55/0.60
TSOP (II)	Thin Small Outline L-Leaded Package (II)	0.50/0.80/1.00/1.27
SON	Small Outline Non-Leaded Package	0.50/1.00
QFP	Quad Flat Package (straight lead) Quad Flat L-Leaded Package	0.40/0.50/0.65/0.80/1.00
LQFP ^{*2}	Low-Profile Quad Flat L-Leaded Package	0.40/0.50/0.65/0.80
TQFP	Thin Quad Flat L-Leaded Package	0.40/0.50
HQFP	QFP with Heat Sink	0.40/0.50/0.65
LCC ^{*2}	Leadless Chip Carrier	1.016/1.27
QFN	Quad Flat Non-Leaded Package	
BGA	Ball Grid Array	1.27/1.0
FBGA	Fine pitch Ball Grid Array	0.8/0.75/0.65/0.5
DTP	Dual Tape Carrier Package	—
QTP	Quad Tape Carrier Package	—

*1: Joint Electron Device Engineering Council

*2: Package name used by Fujitsu Microelectronics

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○ : New product, ⊙ : Now planning

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○ S30MS512R25TFW00	70	-
○ S30MS512R25TFW01	70	-
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SBSF03ABPL	22	-
T021 series	12	-
V08 series	12	-
V09 series	12	-
V10x series	12	-
VC-90 series	12	-

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